Practical Channel Modeling for High-speed Design

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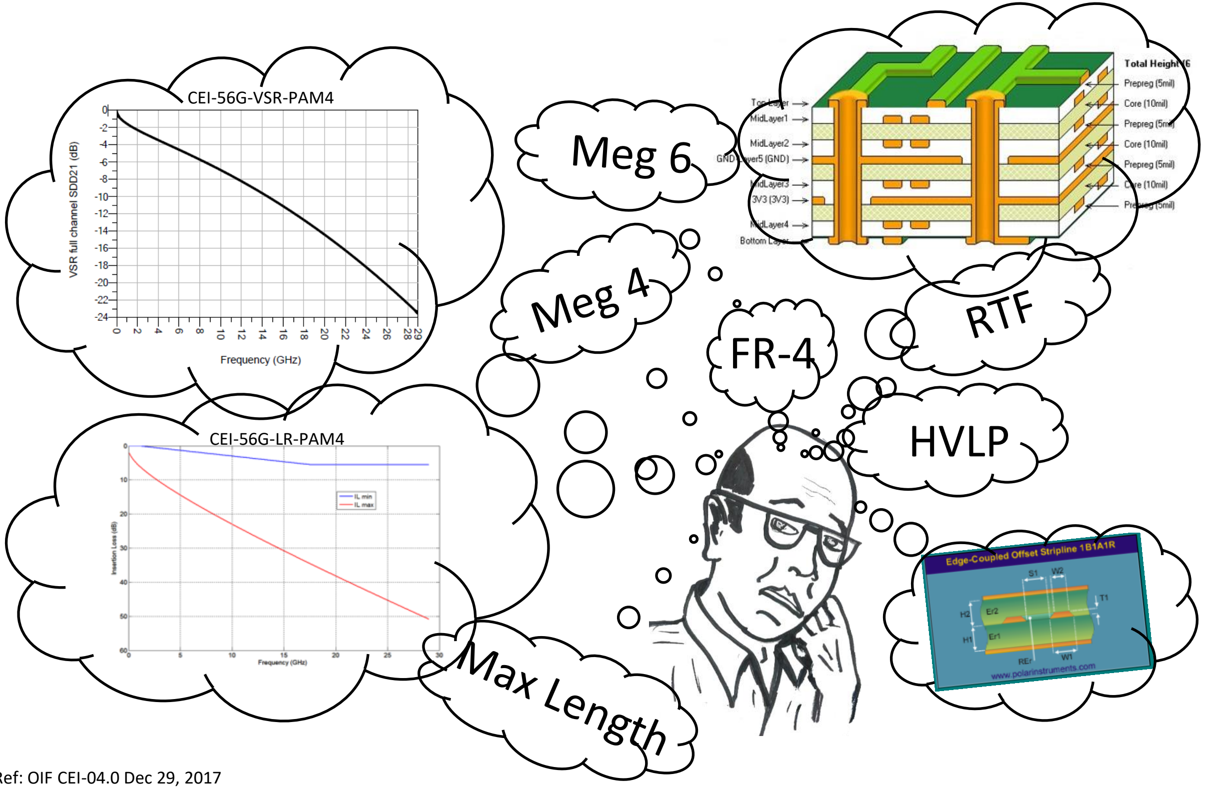
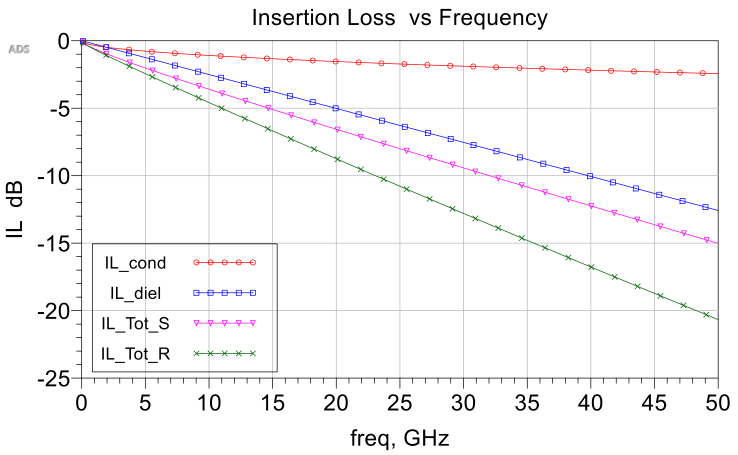
High-level Design Challenges



Choosing appropriate diff pair geometry, board material and stackup to meet insertion loss budgets for industry standards can be overwhelming

Ref: OIF CEI-04.0 Dec 29, 2017

Transmission Line Modeling

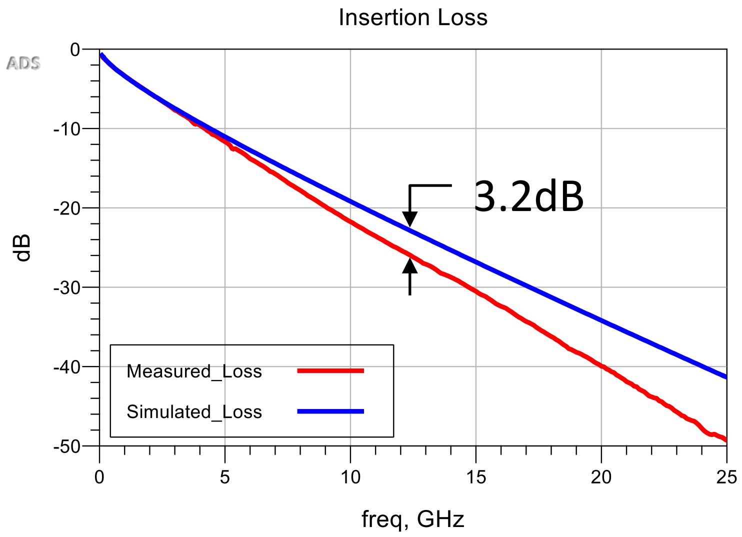


Important to model dielectric and conductor loss accurately

$$IL_{total}(f) = IL_{diel}(f) + K_{SR}(f) \times IL_{conductor}(f)$$

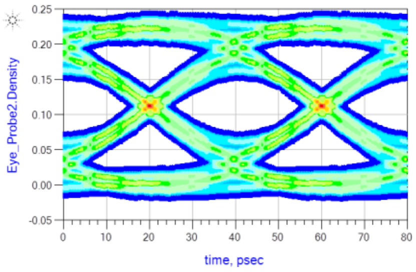
Simulated with Keysight ADS [13]

Failure To Model Roughness Properly Can Ruin You Day!

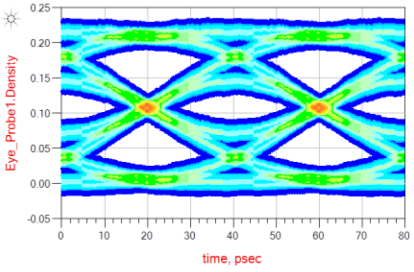


With just 3.2dB delta @12.5 GHz => ½ the eye height with rough copper

Smooth Copper



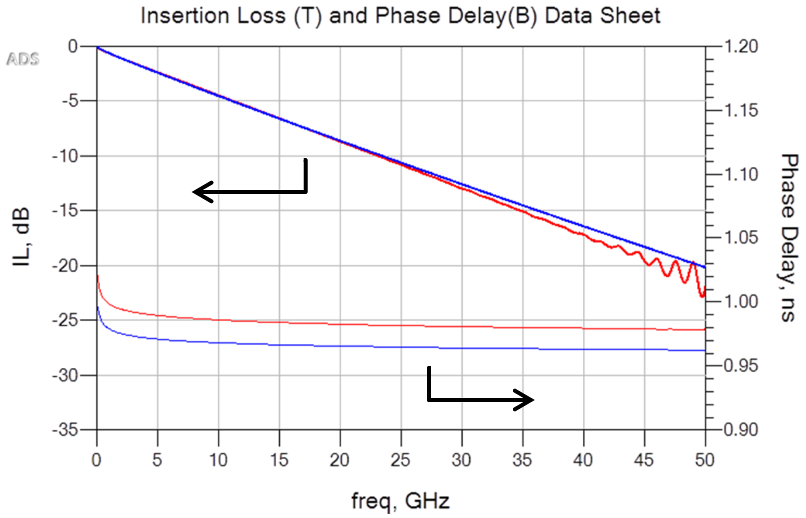
Rough Copper



25Gb/s

Simulated with Keysight ADS [13]

Dielectric Properties



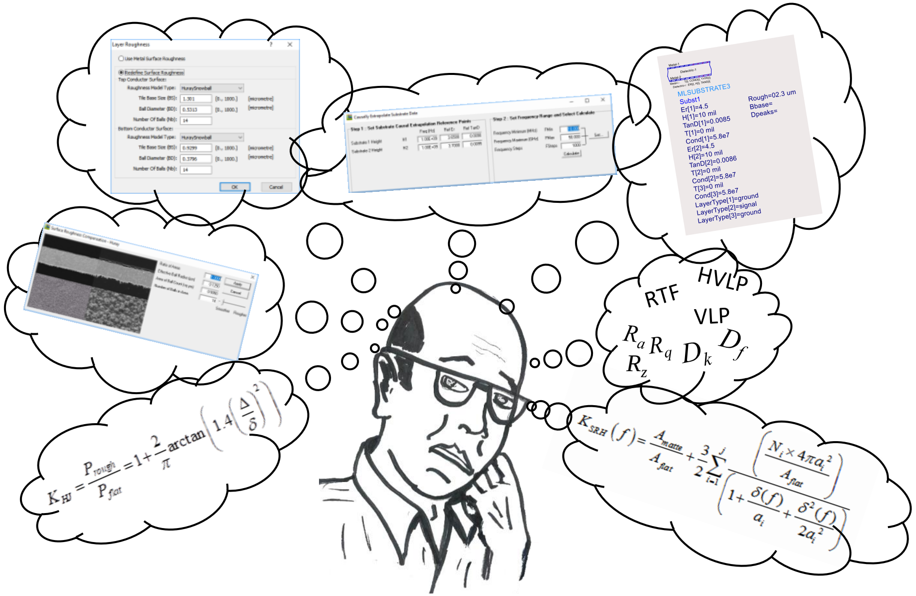
---- Measured ---- Simulated

Failure to correct D_k from data sheet due to conductor roughness => inaccuracy in simulated IL & Phase Delay

Simulated with Keysight ADS [13]

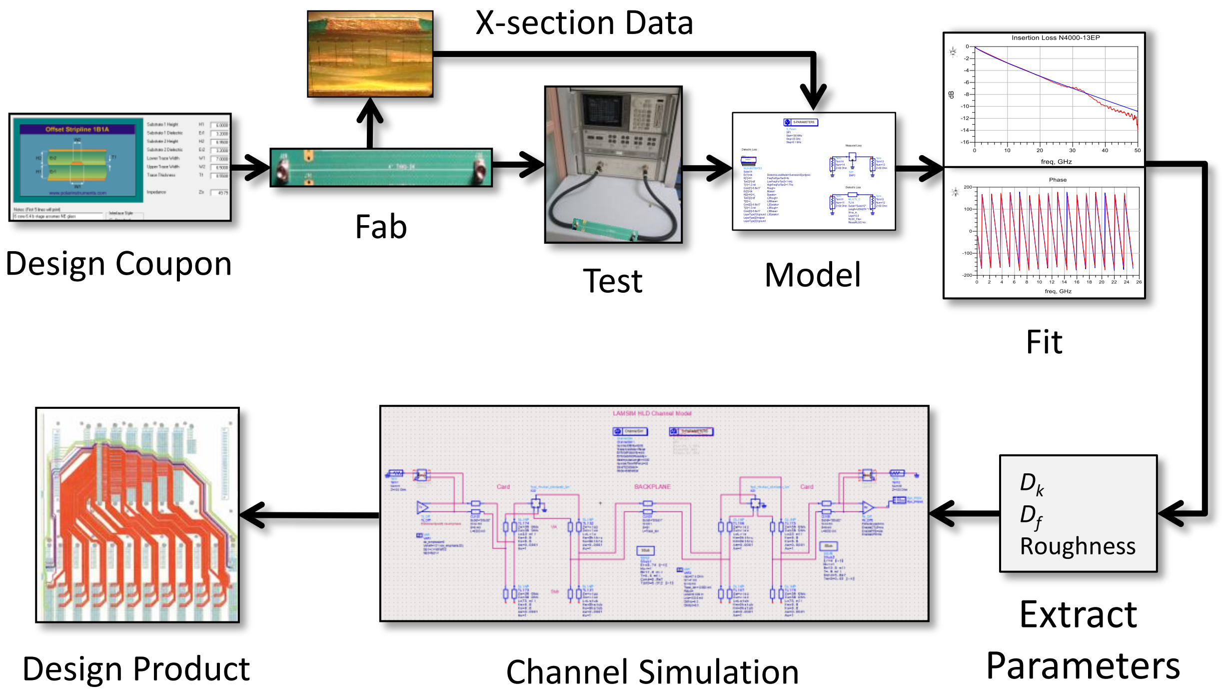
EDA Tool Challenges

✓ **Many EDA tools include latest and greatest models for conductor surface roughness and wideband dielectric properties**



But obtaining the right parameters to feed models is always a challenge

Design Feedback Method



Benefits:

- Practical
- Accurate

Issues:

- Expertise required
- Time
- Money
- Extracted parameters only accurate for sample from which they were extracted

***"Sometimes an OK answer NOW! is better than a good answer late…."* – Eric Bogatin**

What You Will Learn

- ✓ How to apply my Cannonball model to determine Huray roughness parameters from data sheet alone
- ✓ How to determine D_{keff} due to roughness from data sheets alone
- ✓ How to apply these parameters in the latest version of Polar Si9000e Field Solver
- ✓ How to pull it all together using Keysight ADS software

Outline

- Overview
- Modeling Conductor Roughness:
  - Hammerstad Model
  - Huray Model
  - Cannonball-Huray Model
- D_{keff} Due to Roughness Model
- Model Validation
- Practical Channel Modeling for High-speed Design Case Study

Overview

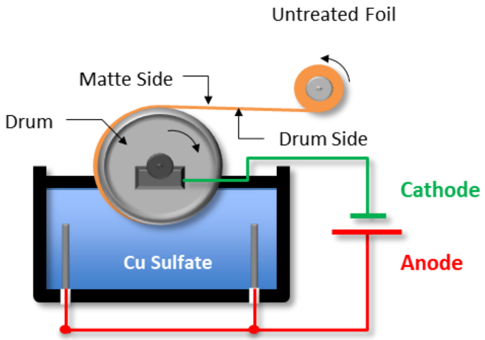
Copper Foil Manufacturing Processes

Rolled

- Smoother
- Higher Cost

VS

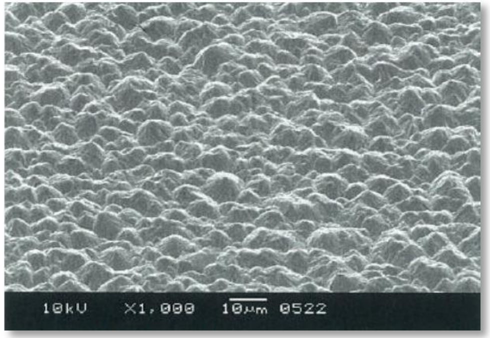
Electro-deposited (ED)



- Rougher
- Lower Cost

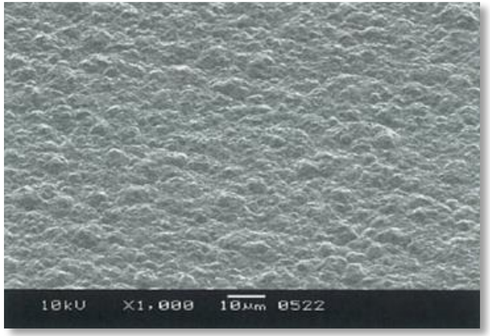
Common ED Roughness Profiles

IPC Standard Profile



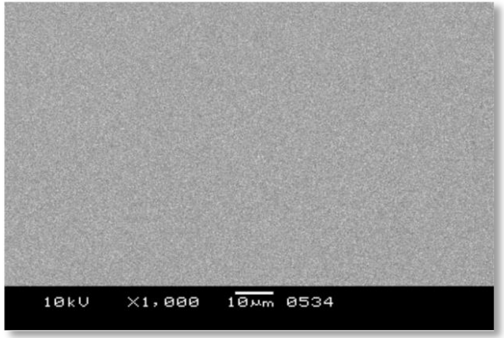
No min/max spec

IPC Very Low Profile(VLP)



< 5.2 μm max

Ultra Low Profile (ULP)Class



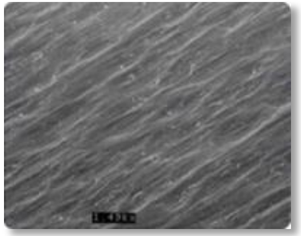
-*Other names: HVLP*, VSP

-No IPC spec

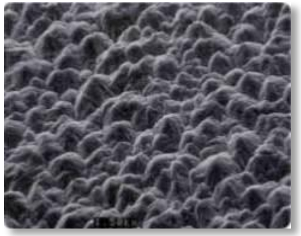
-Typically < 2 μm max

SEM Photos Reference [17]

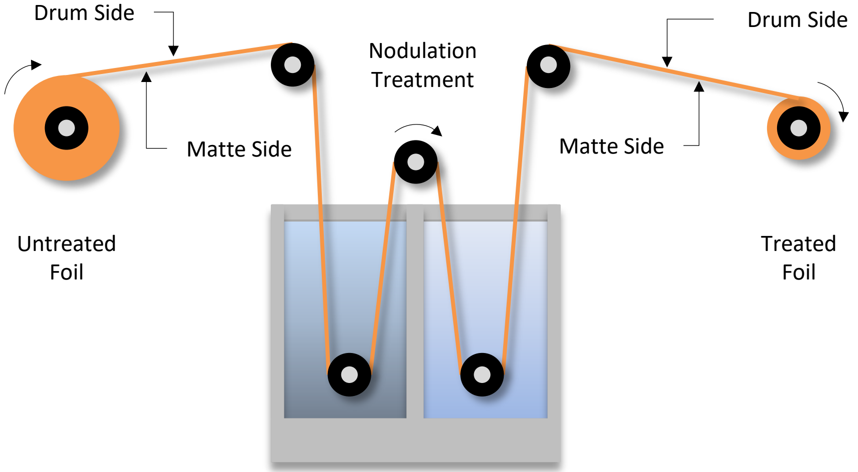
ED Copper Foil Nodulation Treatment

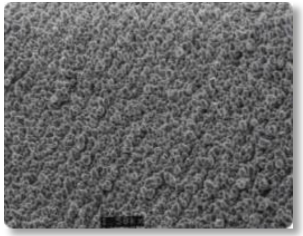


Drum Side Untreated



Matte Side Untreated





Drum Side Treated

OR

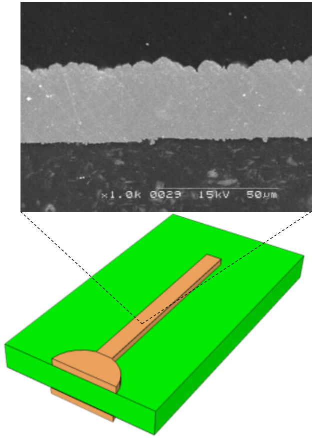
Matte Side Treated

SEM Photos Reference [11]

Oxide/Oxide Alternative Treatment

During PCB fabrication untreated copper on each side of core laminate undergoes a roughening treatment to promote adhesion

50-70 μin copper removal smoothens macro-roughness and adds micro-roughness voids to surface



→ Cleaner → Rinse → Predip → OA → Rinse → Drying →

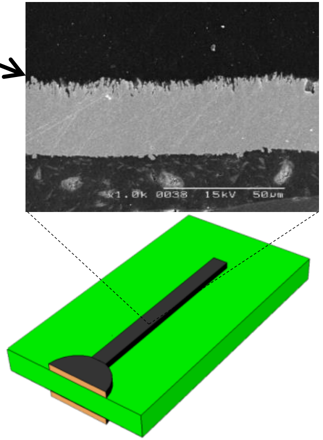
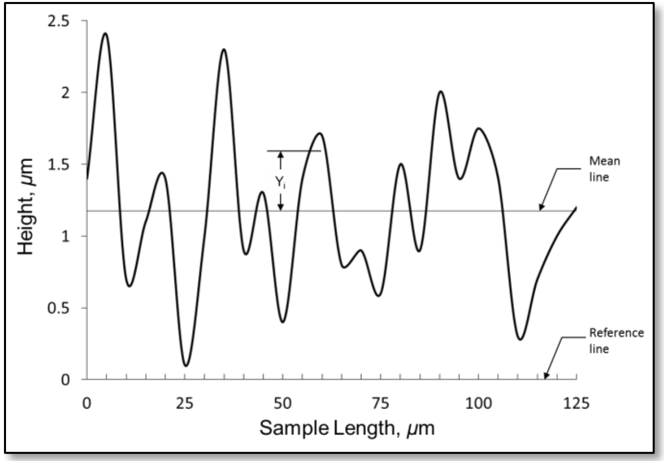


Photo Reference [18]

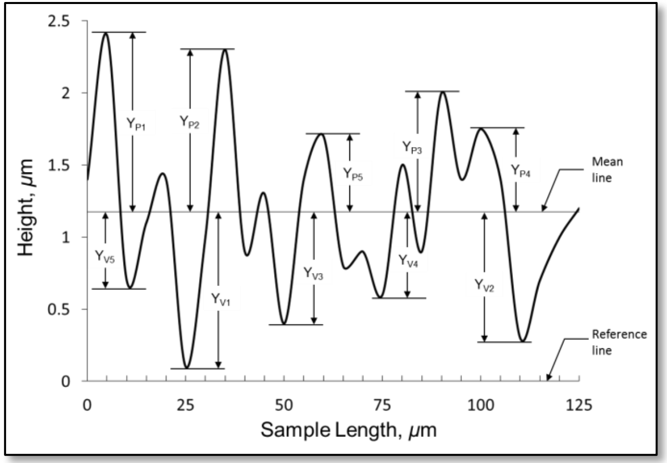
Roughness Parameters

RMS (R_q) / Average (R_a)



$$R_q = \sqrt{\frac{1}{N}\sum_{i=1}^{N} Y_i^2} \qquad R_a = \frac{1}{N}\sum_{i=1}^{N} |Y_i|$$

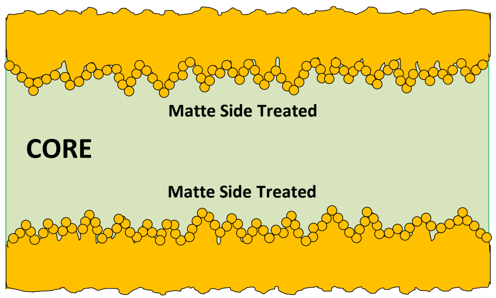
10-point Mean (R_z)



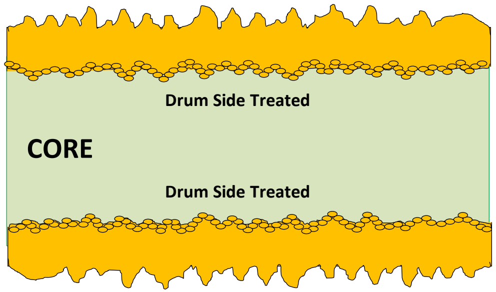
$$R_z = \frac{1}{5}\sum_{i=1}^{5} |Y_{Pi}| + \frac{1}{5}\sum_{i=1}^{5} |Y_{Vi}|$$

Foil Bonding to Core

Standard Treated Foil



Reverse Treated Foil (RTF)



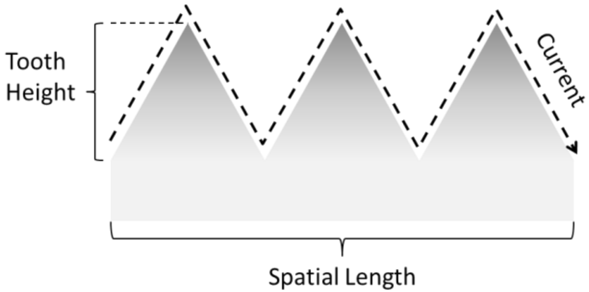
✓ **Treated Side of Raw Foil Always Bonds to Core**

Modeling Conductor Roughness

"All models are wrong but some are useful…"

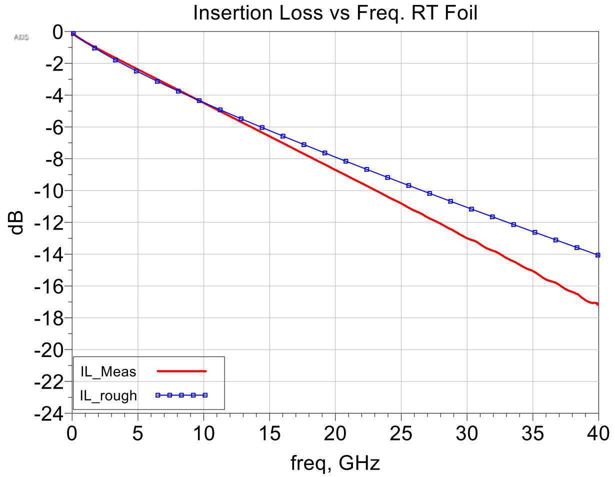
- Sir David Roxbee Cox

Hamerstad & Jenson Model



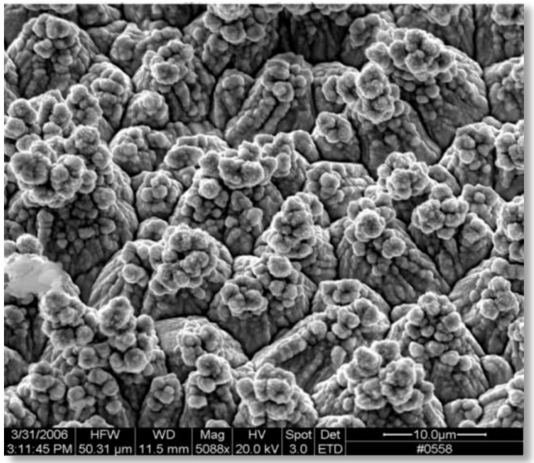
$$K_{HJ} = \frac{P_{rough}}{P_{flat}} = 1 + \frac{2}{\pi}\arctan\left(1.4\left(\frac{\Delta}{\delta}\right)^2\right)$$

$\Delta =$ RMS tooth height in meters



Loses accuracy above ~ 3-15GHz depending on roughness of copper

Huray “*snowball*” Model [5]

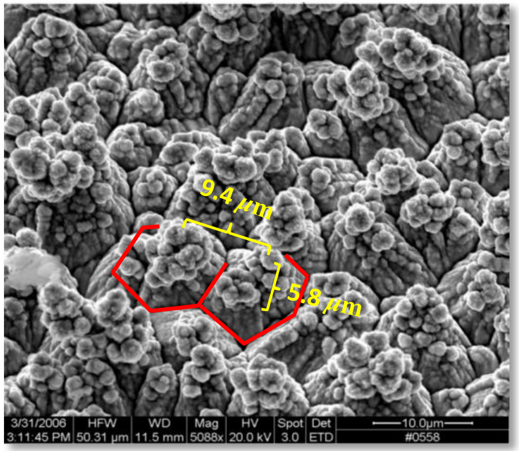


SEM Photo Reference [15]

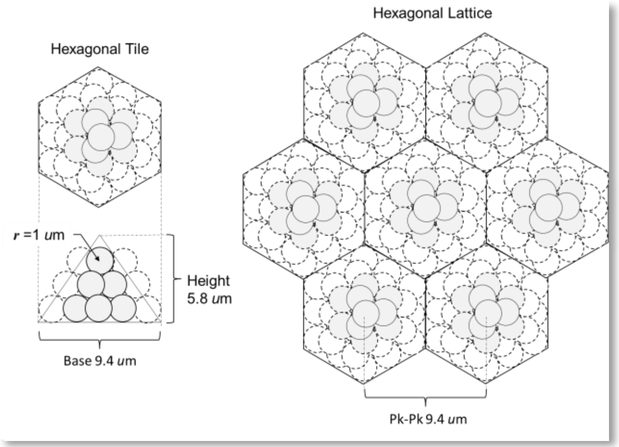
Based on non-uniform distribution of spheres resembling “snowballs” applied to a matte base

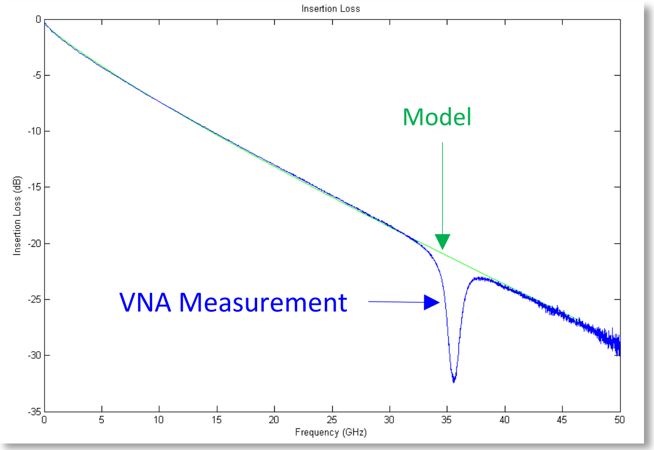
$$K_{SRH}(f) = \frac{P_{rough}}{P_{flat}} \approx \frac{A_{matte}}{A_{flat}} + \frac{3}{2}\sum_{i=1}^{j}\left(\frac{N_i \times 4\pi a_i^{\,2}}{A_{flat}}\right)\left(1 + \frac{\delta(f)}{a_i} + \frac{\delta^2(f)}{2a_i^{\,2}}\right)^{-1}$$

Huray Model Prior Art [6]



SEM Photo Reference [15]





Plot Reference [15]

Assumes stacked "snowballs" arranged in hexagonal lattice

11 spheres min; 38 spheres max of radius 1μm to fit within hex tile area and height of 5.8μm

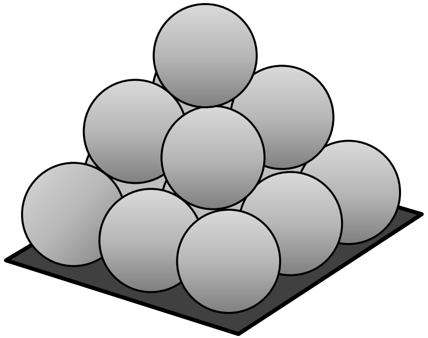
Fit equation parameters to measured data

Cannonball-Huray Model [3]

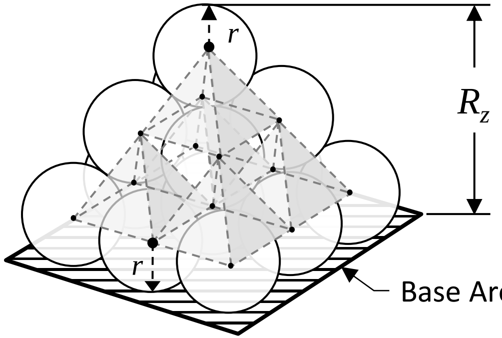
$$K_{SRH}(f)=\frac{A_{matte}}{A_{flat}}+\frac{3}{2}\sum_{i=1}^{j}\frac{\left(\frac{N_i\times 4\pi r^2}{A_{flat}}\right)}{\left(1+\frac{\delta(f)}{r}+\frac{\delta^2(f)}{2r^2}\right)}$$

$$K_{CH}(f)\approx 1+\frac{3}{2}\frac{\left(\frac{14\times 4\pi r^2}{36r^2}\right)}{\left(1+\frac{\delta(f)}{r}+\frac{\delta^2(f)}{2r^2}\right)}$$

$$K_{CH}(f)\approx 1+\left[\frac{2.33\pi}{\left(1+\frac{\delta(f)}{r}+\frac{\delta^2(f)}{2r^2}\right)}\right]$$



N_i=14 Spheres



$$r\approx 0.06(R_z);A_{flat}\approx 36(r)^2$$

Modeling D_{keff} Due to Surface Roughness

Marketing Data Sheet Issues

Property		Typical Value	Specification	Units Metric (English)	Test Method IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		200	170-200	°C	2.4.25
Decomposition Temperature (Td) by TGA @ 5% weight loss		360	–	°C	ASTM D3850
T260		60	–	Minutes	ASTM D3850
T288		>30	–	Minutes	ASTM D3850
CTE, Z-axis	A. Pre-Tg B. Post-Tg	55 230	AABUS –	ppm/°C	2.4.24
CTE, X-, Y-axes	A. Pre-Tg B. Post-Tg	16 18	AABUS –	ppm/°C	2.4.24
Z-axis Expansion (50-260°C)		2.8	–	%	2.4.24
Thermal Conductivity		0.4	–	W/mK	ASTM D5930
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	Rating	2.4.13.1
Dk, Permittivity (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline)	3.72 3.69 3.68 3.64 3.65	5.4 – – – –	–	2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5
Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline)	0.0072 0.0091 0.0092 0.0098 0.0095	0.035 – – – –	–	2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5
Volume Resistivity	A. 96/35/90 B. After moisture resistance C. At elevated temperature	– $4.4x10^7$ $9.4x10^7$	$1.0x10^6$ – $1.0x10^3$	MΩ-cm	2.5.17.1
Surface Resistivity	A. 96/35/90 B. After moisture resistance C. At elevated temperature	– $2.6x10^6$ $2.1x10^8$	$1.0x10^4$ – $1.0x10^3$	MΩ	2.5.17.1
Dielectric Breakdown		>50	–	kV	2.5.6
Arc Resistance		137	60	Seconds	2.5.1
Electric Strength (Laminate & prepreg as laminated)		70 (1741)	30 (750)	kV/mm (V/mil)	2.5.6.2
Comparative Tracking Index (CTI)		3 (175-249)	–	Class (Volts)	UL-746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile – all copper weights >17 microns B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions	1.14 (6.5) – 0.96 (5.5) – 0.90 (5.1)	0.70 (4.0) – 0.80 (4.5) 0.70 (4.0) 0.55 (3.0)	N/mm (lb/inch)	2.4.8 2.4.8.2 2.4.8.3 – –
Flexural Strength	A. Lengthwise direction B. Crosswise direction	72,500 58,000	–	$lb/inch^2$	2.4.4
Tensile Strength	A. Lengthwise direction B. Crosswise direction	54,525 38,678	–	$lb/inch^2$	–
Young's Modulus	A. Grain direction B. Fill direction	3695 3315	–	ksi	ww
Poisson's Ratio	A. Grain direction B. Fill direction	0.137 0.133	–	–	xx
Moisture Absorption		0.061	–	%	2.6.2.1
Flammability (Laminate & prepreg as laminated)		V-0	–	Rating	UL 94
Max Operating Temperature		130	UL Cert	°C	–

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

Dk, Permittivity (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline)	3.72 3.69 3.68 3.64 3.65	5.4 – – – –	–	2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5
Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline)	0.0072 0.0091 0.0092 0.0098 0.0095	0.035 – – – –	–	2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5

Using Dk/Df numbers from marketing data sheets for stackup and channel modeling will give inaccurate results

Reference: Isola [9]

Engineering Data Sheets

Core Data

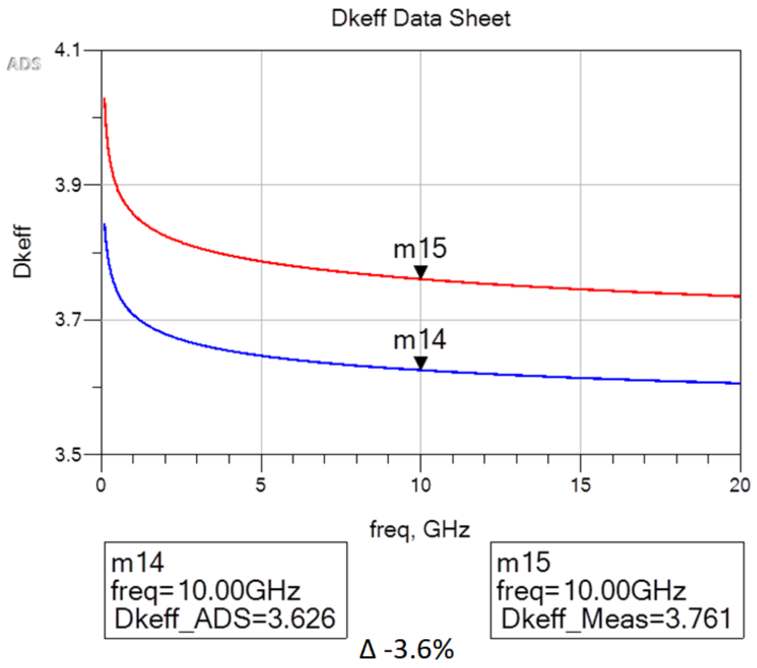
Core Constructions	Resin Content (%)	Thickness (inch)	Thickness (mm)	Dielectric Constant(DK) / Dissipation Factor(DF) 100 MHz	500 MHz	1.0 GHz	2.0 GHz	5.0 GHz	10.0 GHz	15.0 GHz	20.0 GHz
1x106	72.0	0.0020 ZBC	0.0508 ZBC	3.37 0.0075	3.36 0.0089	3.34 0.0096	3.32 0.0101	3.30 0.0107	3.30 0.0107		
1x1067	69.0	0.0025	0.0635	3.42 0.0075	3.40 0.0084	3.38 0.0095	3.36 0.0100	3.34 0.0105	3.33 0.0104		
1x1080	57.0	0.0025	0.0635	3.67 0.0071	3.64 0.0079	3.62 0.0089	3.61 0.0092	3.60 0.0097	3.59 0.0095		
1x1086	58.0	0.0030	0.0762	3.65 0.0072	3.63 0.0079	3.60 0.0091	3.59 0.0092	3.57 0.0098	3.57 0.0095		
1x1080	63.0	0.0030	0.0762	3.54 0.0074	3.52 0.0082	3.50 0.0092	3.48 0.0096	3.47 0.0102	3.47 0.0101		
1x3313	51.0	0.0035	0.0889	3.82 0.0068	3.79 0.0076	3.77 0.0084	3.77 0.0087	3.74 0.0092	3.74 0.0090		
2x106	67.0	0.0035	0.0889	3.46 0.0074	3.45 0.0083	3.42 0.0094	3.40 0.0098	3.38 0.0104	3.37 0.0102		
106/1080	59.0	0.0040	0.1016	3.63 0.0072	3.61 0.0080	3.58 0.0090	3.57 0.0093	3.55 0.0098	3.54 0.0096		
1x3313	55.0	0.0040	0.1016	3.72 0.0071	3.70 0.0077	3.68 0.0087	3.66 0.0090	3.65 0.0095	3.65 0.0094		
106/1080	61.0	0.0043	0.1092	3.57 0.0073	3.56 0.0081	3.54 0.0092	3.52 0.0095	3.51 0.0099	3.50 0.0098		
2x1067	63.0	0.0043	0.1092	3.54 0.0074	3.52 0.0082	3.50 0.0092	3.48 0.0096	3.47 0.0102	3.47 0.0101		
106/1080	62.0	0.0045	0.1143	3.55 0.0073	3.54 0.0082	3.52 0.0092	3.50 0.0095	3.48 0.0100	3.48 0.0098		

Provides:

- ✓ Actual core/prepreg thicknesses
- ✓ Resin content
- ✓ Dk(f) /Df(f) for different glass styles

Reference: Isola [9]

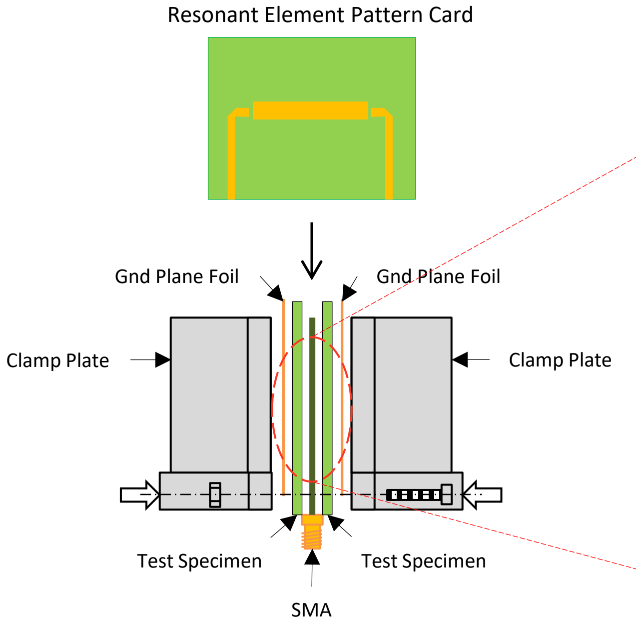
Dielectric Modeling Issue



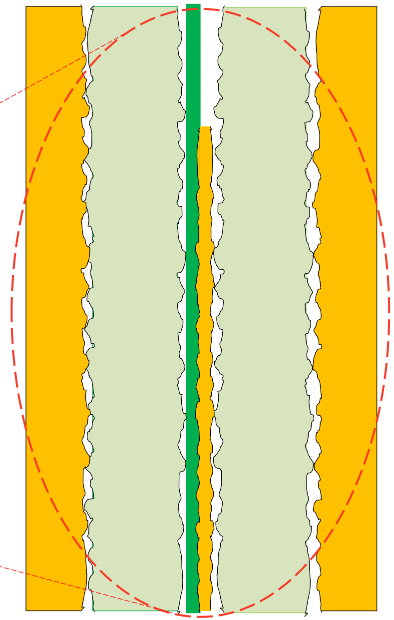
When Data Sheet D_k is not the same as Effective D_k

Simulated with Keysight ADS [13]

IPC-TM-650 Clamped Stripline Resonator Test Method [14]



Side View (Unclamped) N.T.S.



Side View (Clamped) N.T.S.

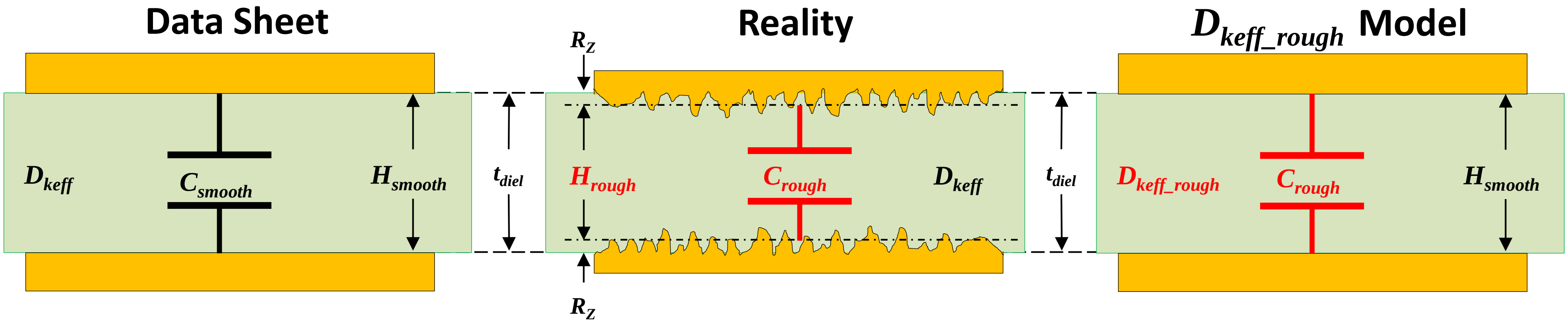
Issue:

Since resonant element pattern card & material U.T. not physically bonded together => small air gaps between various layers & conductor roughness affects published results

Published D_k not same as D_{keff} due to roughness

IPC-TM-650 - Section 2.5.5.5 - Rev C - Test Fixture [14]

D_{keff} Due to Roughness Model [1]



$$C_{smooth} = D_{keff}\left(\frac{\varepsilon_0 A}{H_{smooth}}\right)$$

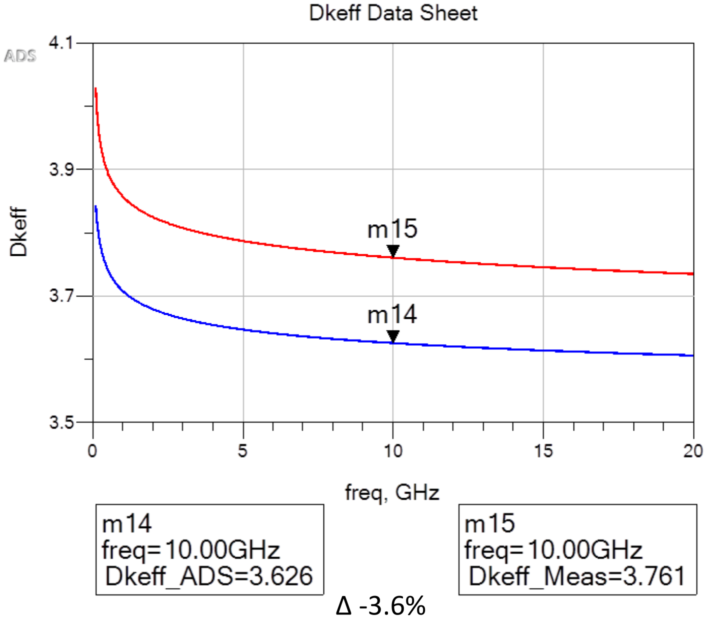
$$C_{rough} = D_{keff}\left(\frac{\varepsilon_0 A}{H_{rough}}\right) = D_{keff}\left(\frac{\varepsilon_0 A}{(H_{smooth} - 2R_z)}\right)$$

$$C_{rough} = D_{keff\_rough}\left(\frac{\varepsilon_0 A}{H_{smooth}}\right)$$

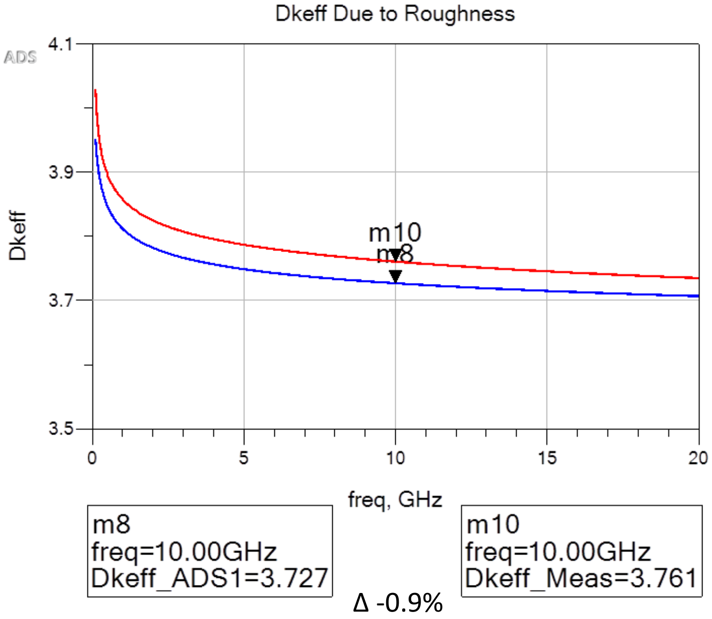
$$\frac{H_{smooth}}{H_{rough}} = \frac{C_{rough}}{C_{smooth}} = \frac{D_{keff\_rough}\left(\frac{\varepsilon_0 A}{H_{smooth}}\right)}{D_{keff}\left(\frac{\varepsilon_0 A}{H_{smooth}}\right)} = \frac{D_{keff\_rough}}{D_{keff}}$$

$$D_{keff\_rough} = \frac{H_{smooth}}{(H_{smooth} - 2R_z)} \times D_{keff}$$

FR408HR/RTF Simulation Results for D_{keff}



Data Sheet Values



D_{keff} Roughness Model

Causal Roughness Correction Factors [4]

Complex impedance of rough metal

Real part of internal impedance of rough metal

Imaginary part of internal impedance of rough metal

$$Z_{rough}(if) = K(if)(1+i)\sqrt{\pi f}\,R_s = [K_{re}(f) - K_{im}(f)]\sqrt{\pi f}\,R_s + i[K_{re}(f) + K_{im}(f)]\sqrt{\pi f}\,R_s$$

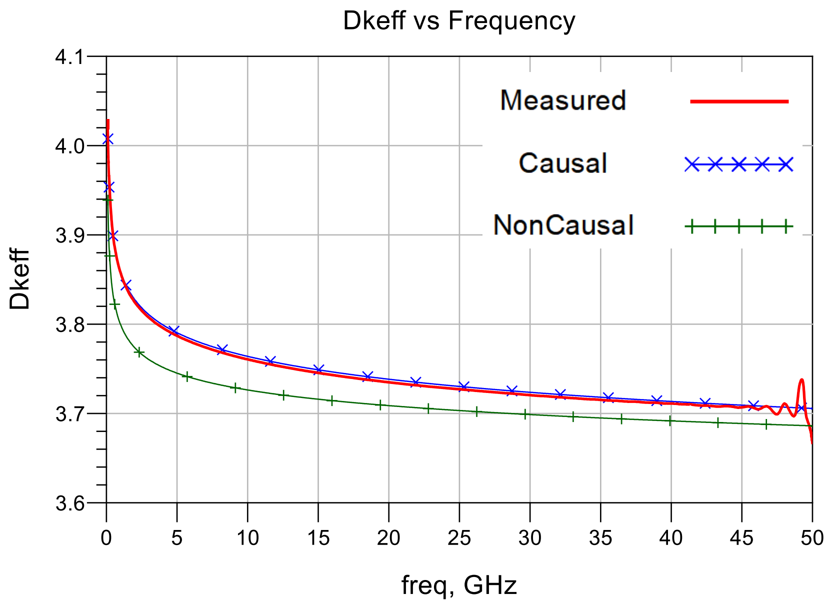
Complex roughness correction factor

Loss correction factor

Inductance correction factor

This is what we used to call "roughness correction" factor

A Causal Conductor Roughness Model and its Effect on Transmission Line Characteristics [4]



D_{keff} corrected due to roughness and complex roughness correction factor applied

✓Excellent Results!

Modeled with Hyperlynx [20] and Simulated with Keysight ADS[13]

Model Validations

CMP-28 Test Platform [7]

Photo courtesy Wild River Technology [7]

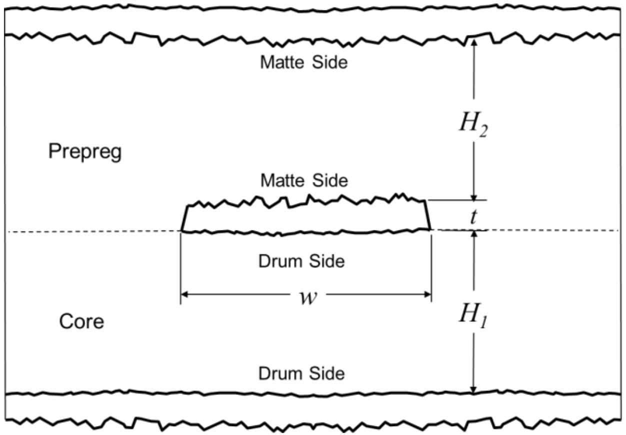
Features:

- FR408HR material with reverse-treated foil (RTF)
- Assembled with 2.92mm (CMP-28) or 2.4mm (CMP-32) connectors
- 3D EM benchmark structures
    - Loss structures for material extraction
    - Resonators for measurement correspondence
    - Multi-impedance structures for VNA time transform analysis

Applications:

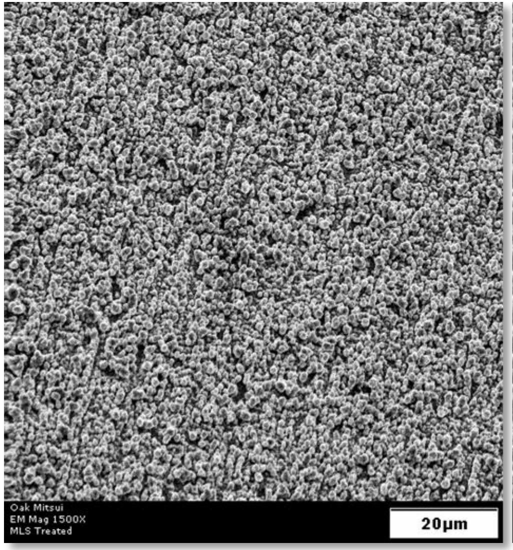
- 3D-EM and measurement assistance for the SI practitioner
    - Vias
    - Multimode Analysis
    - Meshing Analysis Structure
    - Advanced Material Extraction and Loss Modeling
- THRU Calibration, T-matrix de- embedding
- Advanced Crosstalk analysis
- TRL/LRM Calibration Verification/Benchmark

FR408HR/RTF Data Sheet & Test Board Design Parameters [7],[9],[11]



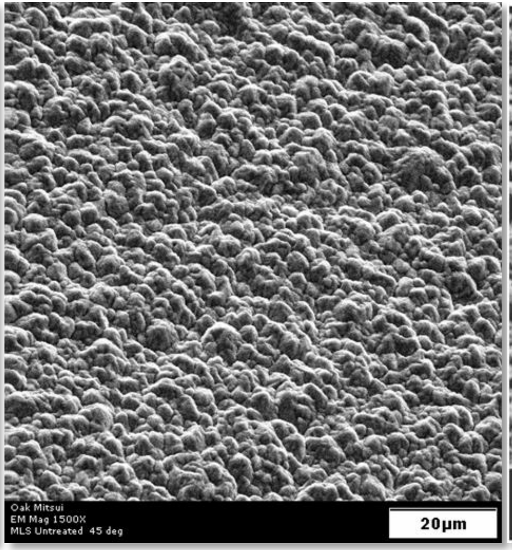
Parameter	FR408HR/RTF
D_k Core/Prepreg	3.65/3.59 @10GHz
D_f Core/Prepreg	0.0094/0.0095 @ 10GHz
R_z Drum side	3.048 μm
R_z Before Micro-etch-Matte side	5.715 μm
R_z After 50 μin (1.27 µm) Micro-etch treatment -Matte side	4.445 μm
Trace Thickness, t	1.25 mils (31.73 μm)
Trace Etch Factor	60 deg taper
Trace Width, w	11 mils (279.20 μm)
Core thickness, H1	12 mils (304.60 μm)
Prepreg thickness, H2	10.6 mils (269.00 μm)
De-embedded trace length	6.00 in (15.24 cm)

MLS RT foil



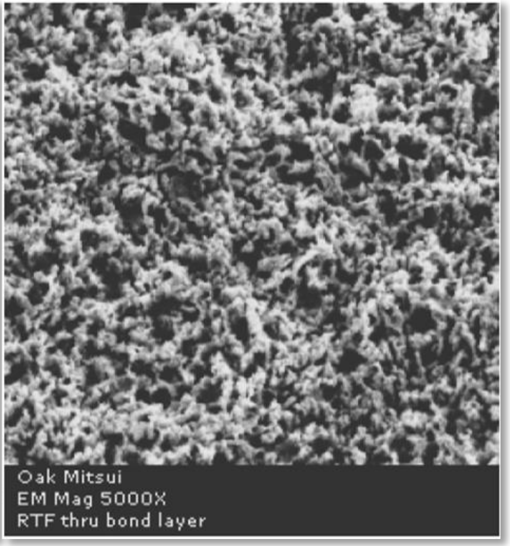
Treated drum side

Rz = 3.175 μm



Untreated matte side

Rz = 5.715 μm

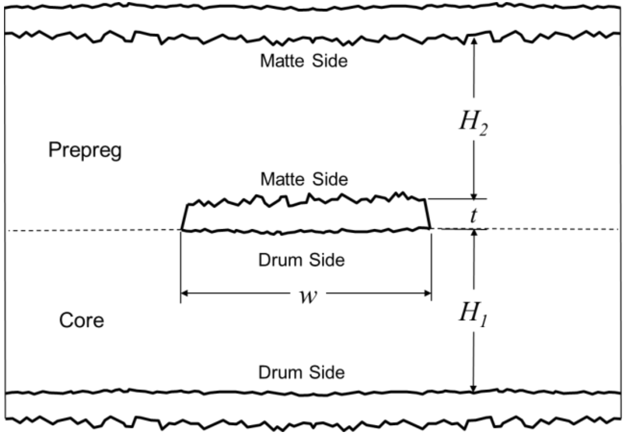


Matte side after etch treatment

Rz = 4.443 μm

Photos courtesy of Oak-mitsui [11]

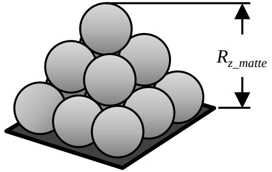
Determine D_{keff} Due to Roughness Core/Prepreg



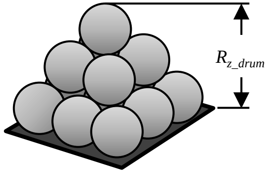
$$D_{keff\_prepreg} = \frac{H_{2\_smooth}}{\left(H_{2\_smooth} - 2R_{z\_matte}\right)} \times D_{k\_prepreg} = \frac{269\mu m}{\left(269\mu m - 2\times 4.445\mu m\right)} \times 3.59 = 3.713$$

$$D_{keff\_core} = \frac{H_{1\_smooth}}{\left(H_{1\_smooth} - 2R_{z\_drum}\right)} \times D_{k\_core} = \frac{304.6\mu m}{\left(304.6\mu m - 2\times 3.048\mu m\right)} \times 3.65 = 3.725$$

Determine Sphere Radius (r) & Base Area (A_{flat})



Matte-side



Drum-side

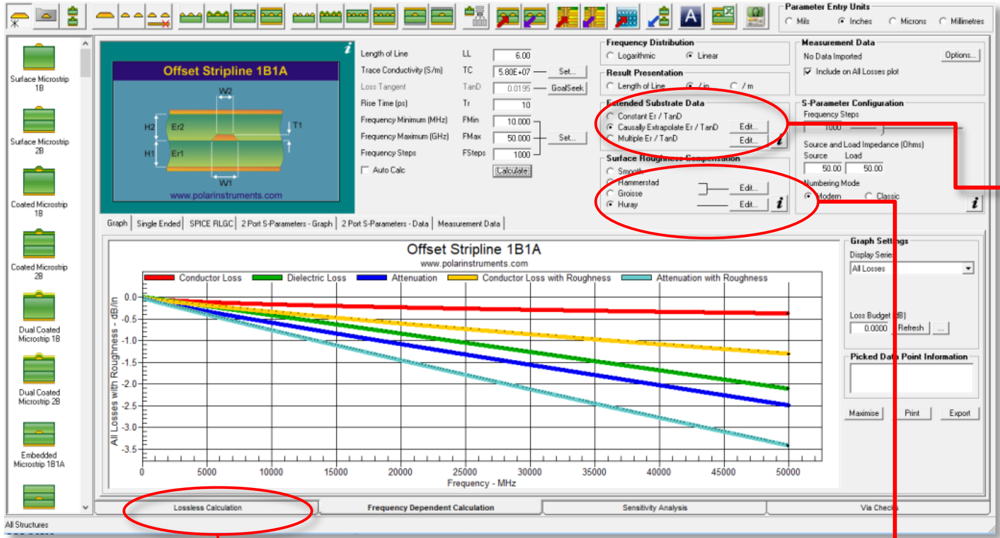
$$
\begin{aligned}
r_{matte} &\approx 0.06 R_{z\_matte} \\
&\approx 0.06 \times 4.443 \mu m \\
&\approx 0.266 \mu m
\end{aligned}
$$

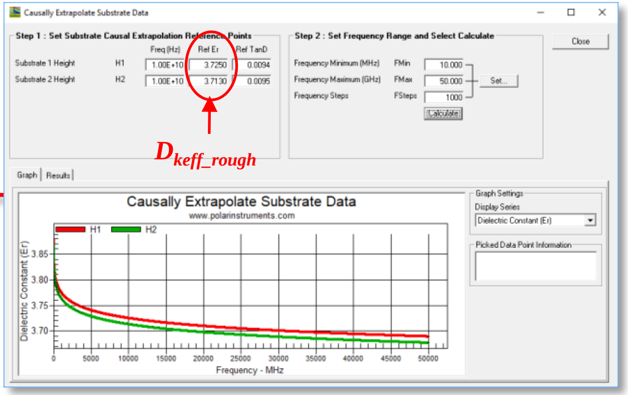
$$
\begin{aligned}
r_{drum} &\approx 0.06 R_{z\_drum} \\
&\approx 0.06 \times 3.048 \mu m \\
&\approx 0.182 \mu m
\end{aligned}
$$

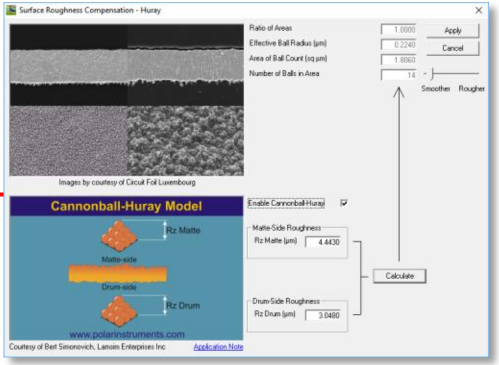
$$
\begin{aligned}
r_{eff} &\approx \frac{r_{matte} + r_{drum}}{2} \\
&\approx \frac{0.266 \mu m + 0.182 \mu m}{2} \\
&\approx 0.224 \mu m
\end{aligned}
$$

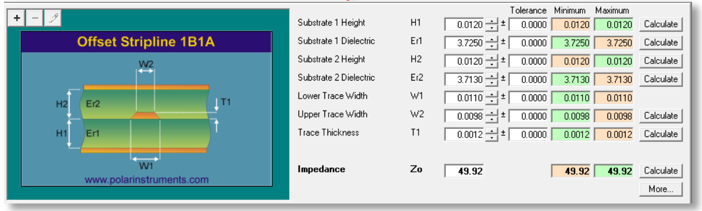
$$
\begin{aligned}
A_{flat} &= 36 \left(r_{eff} \right)^2 \\
&= 36 (0.224 \mu m)^2 \\
&= 1.806 \mu m^2
\end{aligned}
$$

Input Design Parameters Polar Si9000e [12]

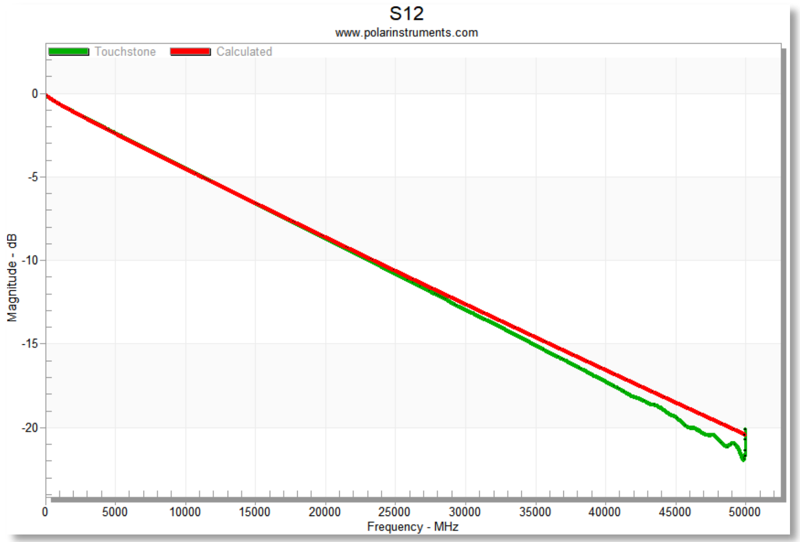




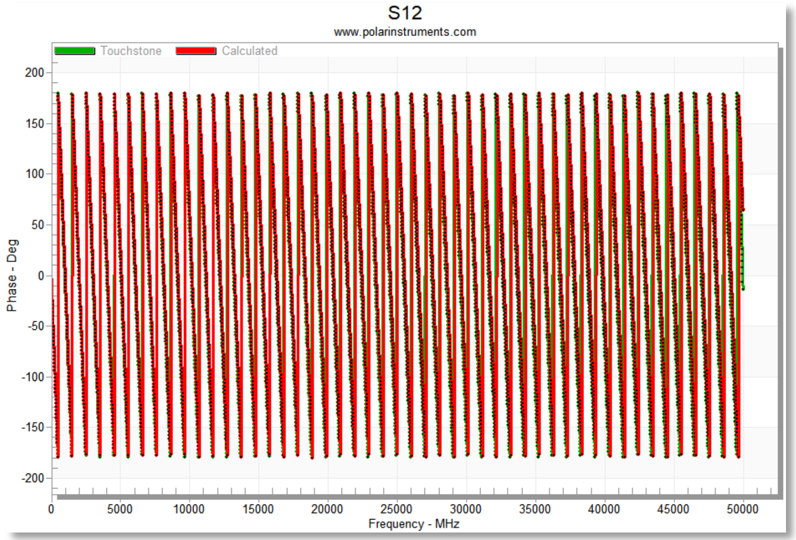




Simulated vs Measured



Insertion Loss

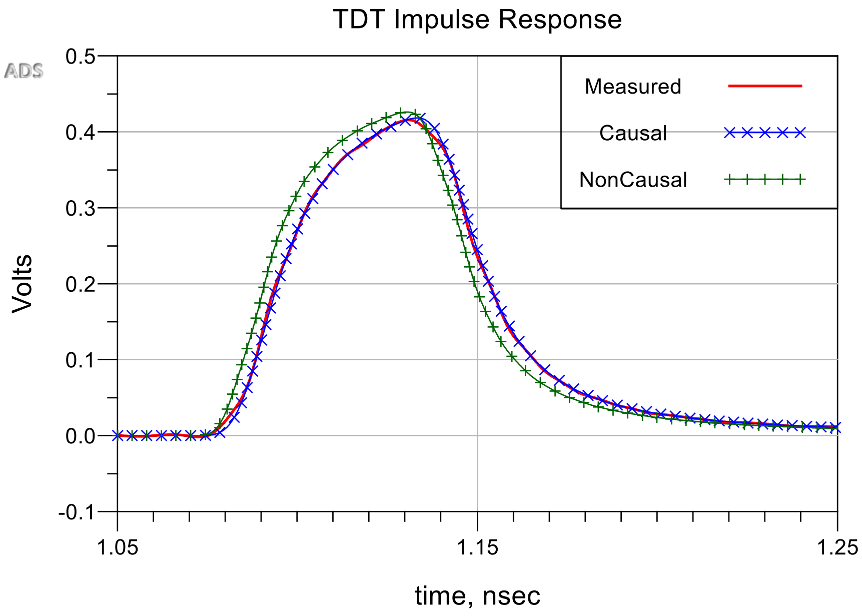


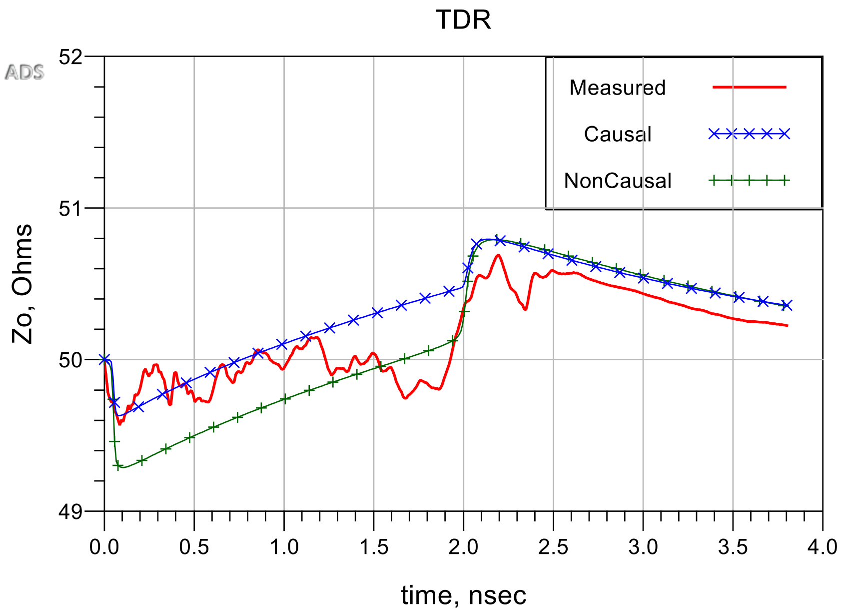
Phase

✓ Excellent Correlation!

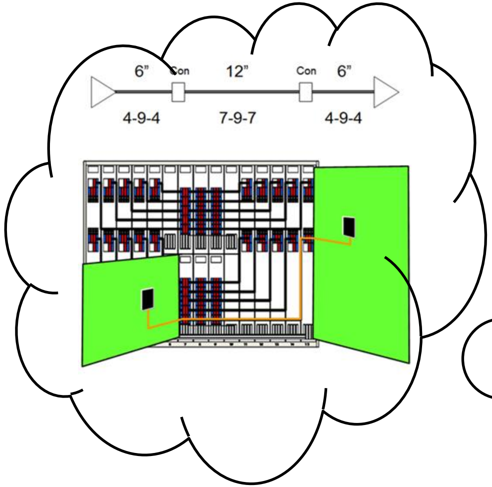
Modeled and Simulated with Polar Si9000e [12]

FR408HR Simulation Results for Impulse and TDR

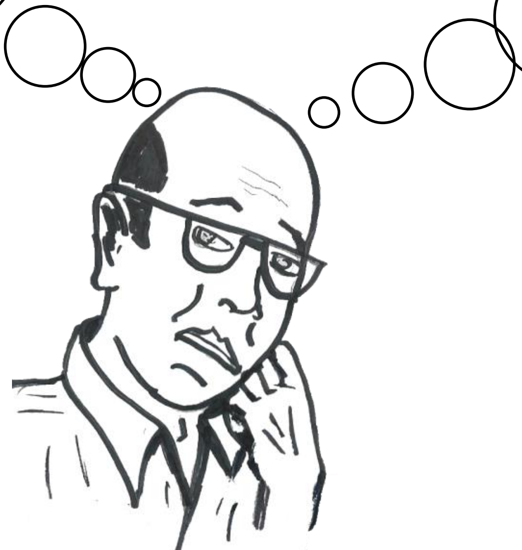




Modeled with Hyperlynx [20] and Simulated with Keysight ADS[13]



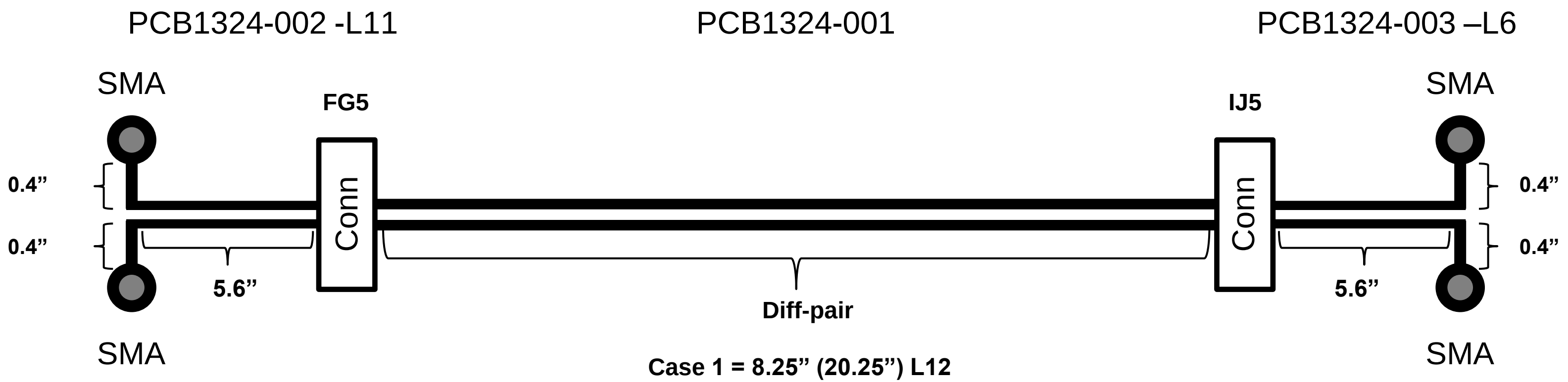
Well…single-ended looks great……BUT how well does this method work to model a practical backplane channel with diff pairs?



ExaMax Demonstrator Platform

- Design Intent - 28 GB/s NRZ
- Meg 6 or N4000-13EPSI Options
  - Nelco N4000-13EPSI Version Used
- MW-G-VSP ½ oz. foil (VLP)
- 2.9 mm coax connectors
- Case 1 = 8.25” (20.25”) L12
- Case 2 = 14.80” (26.8”) L10
- Case 3 = 20.22” (32.22”) L10
- Case 4 = 26.70” (38.70”) L12

Loss Topology Model N4000-13EPSI Summary



Case 1 = 8.25” (20.25”) L12
Case 2 = 14.80” (26.8”) L10
Case 3 = 20.22” (32.22”) L10
Case 4 = 26.70” (38.70”) L12

W = 4.9mils
S = 6.1mils
t = 0.6 mils

W = 6.3mils()
S = 5.7 mils()
t = 0.6 mils()

W = 4.9mils
S = 6.1mils
t = 0.6 mils

Data Sheet Parameters [10], [11]

PARK ELECTROCHEMICAL CORP.

N4000-13 SI® / N4000-13EP SI® – Dielectric Properties Table

	Thickness & Tol.	Construction	RC%	2GHz Dk	2 GHz Df	10 GHz Dk	10 GHz Df
	0.0020 ± 0.0005	1 106	69%	3.04 ± 0.056	0.0082 ± 0.00021	3.02 ± 0.055	0.0086 ± 0.00023
	0.0020 ± 0.0005	1 1035	67%	3.07 ± 0.024	0.0081 ± 0.00009	3.04 ± 0.024	0.0085 ± 0.00010
	0.0025 ± 0.0005	1 1078	58%	3.19 ± 0.037	0.0077 ± 0.00014	3.16 ± 0.037	0.0080 ± 0.00016
	0.0030 ± 0.0005	1 1078	64%	3.11 ± 0.020	0.0079 ± 0.00007	3.08 ± 0.020	0.0083 ± 0.00008
	0.0025 ± 0.0005	1 1080	58%	3.19 ± 0.048	0.0077 ± 0.00018	3.16 ± 0.048	0.0080 ± 0.00020
	0.0030 ± 0.0005	1 1080	64%	3.11 ± 0.029	0.0079 ± 0.00011	3.08 ± 0.029	0.0083 ± 0.00012
	0.0035 ± 0.0005	1 2013	50%	3.29 ± 0.027	0.0072 ± 0.00010	3.27 ± 0.027	0.0075 ± 0.00011
DC Core	0.0040 ± 0.0005	2 1035	67%	3.07 ± 0.010	0.0081 ± 0.00004	3.04 ± 0.010	0.0085 ± 0.00004
	0.0040 ± 0.0005	1 2013	57%	3.19 ± 0.012	0.0076 ± 0.00005	3.17 ± 0.012	0.0079 ± 0.00005
	0.0040 ± 0.0005	1 2116	45%	3.38 ± 0.029	0.0069 ± 0.00011	3.35 ± 0.029	0.0072 ± 0.00012
	0.0050 ± 0.0007	1 2116	56%	3.21 ± 0.001	0.0076 ± 0.00000	3.18 ± 0.001	0.0079 ± 0.00001
	0.0050 ± 0.0007	2 1078	58%	3.19 ± 0.015	0.0077 ± 0.00006	3.16 ± 0.015	0.0080 ± 0.00006
	0.0060 ± 0.0007	2 1078	64%	3.11 ± 0.004	0.0079 ± 0.00002	3.08 ± 0.004	0.0083 ± 0.00002
	0.0050 ± 0.0007	2 1080	58%	3.19 ± 0.026	0.0077 ± 0.00010	3.16 ± 0.026	0.0080 ± 0.00011
BP Core	0.0060 ± 0.0007	2 1080	64%	3.11 ± 0.013	0.0079 ± 0.00005	3.08 ± 0.013	0.0083 ± 0.00006
	0.0070 ± 0.001	2 2013	50%	3.29 ± 0.027	0.0072 ± 0.00010	3.27 ± 0.027	0.0075 ± 0.00011

	Glass	RC%	2 GHz Dk	2GHz Df	10GHz Dk	10GHz Df	Thickness (inches)
	106	75	2.98	0.0084	2.95	0.0088	0.0025
	1035	75	2.98	0.0084	2.95	0.0088	0.0030
	1078	65	3.09	0.0080	3.06	0.0084	0.0032
BP/DC Prepreg	1080	65	3.09	0.0080	3.06	0.0084	0.0032
	2013	58	3.18	0.0077	3.15	0.0080	0.0044
	2116	55	3.22	0.0075	3.19	0.0078	0.0052

OAK-MITSUI *Performance Copper Foils*

MITSUI KINZOKU CORPORATE GROUP

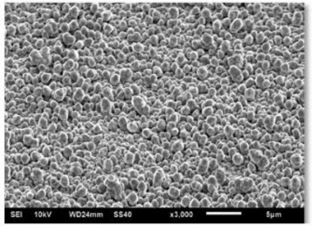
MITSUI KINZOKU

MW–G–VSP

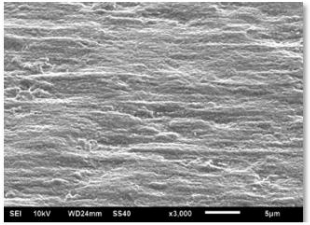
	μm	Rz (μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
MW–G–VSP	18	2.5	350	8	1.0 ←
	35	2.5	350	16	1.3
	70	2.5	350	19	1.5

※表中の数値は代表値です。保証値ではありません。
This is representative date, not guarantee.

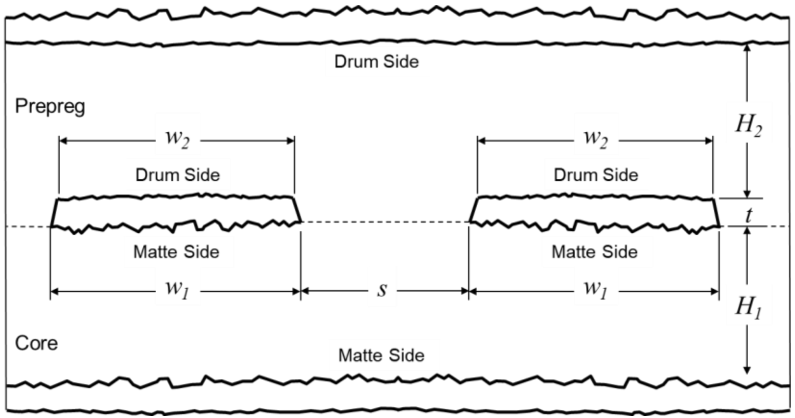
ラミ面/Laminate side



レジ面 / resist side

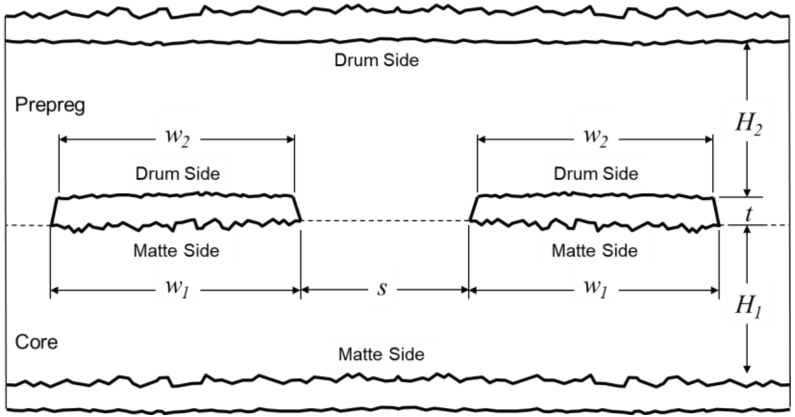


ExaMax Demonstrator Platform
Data Sheet Design Parameters Summary



Parameter	N4000-13EPSI Backplane	N4000-13EPSI Daughter Card
D_k Core/Prepreg @ $10GHz$	3.08/3.06	3.04/3.06
D_f Core/Prepreg @ $10GHz$	0.0083/0.0084	0.0085/0.0084
R_z Matte side	2.5 μm	2.5μm
R_z Drum side w/OA	1.5 μm	1.5 μm
Trace Thickness, t	0.6 mils	0.6 mils
Trace Width, w_1	6.3 mils	4.9 mils (Diff) 5.4 mils (SE)
Trace Width, w_2	5.7 mils	4.3 mils (Diff) 4.8 mils (SE)
Trace Separation, s	5.7 mils	6.1 mils
Core thickness, H1	6 mils	4 mils
Prepreg thickness, H2	5.8 mils	5.8 mils

Determine D_{keff} Due to Roughness Core/Prepreg



Daughter Card

$$D_{keff\_prepreg} = \frac{H_{smooth}}{\left(H_{smooth} - 2R_{z\_drum}\right)} \times D_{k\_prepreg} = \frac{6.2mils \times 25.4}{\left(6.2mils \times 25.4 - 2 \times 1.5\mu m\right)} \times 3.06 = 3.12$$

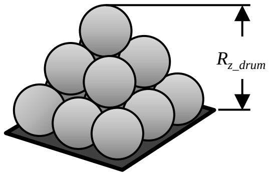
$$D_{keff\_core} = \frac{H_{smooth}}{\left(H_{smooth} - 2R_{z\_matte}\right)} \times D_{k\_core} = \frac{4.0mils \times 25.4}{\left(4.0mils \times 25.4 - 2 \times 2.5\mu m\right)} \times 3.04 = 3.20$$

Backplane

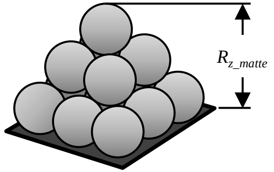
$$D_{keff\_prepreg} = \frac{H_{smooth}}{\left(H_{smooth} - 2R_{z\_drum}\right)} \times D_{k\_prepreg} = \frac{6.2mils \times 25.4}{\left(6.2mils \times 25.4 - 2 \times 1.5\mu m\right)} \times 3.06 = 3.12$$

$$D_{keff\_core} = \frac{H_{smooth}}{\left(H_{smooth} - 2R_{z\_matte}\right)} \times D_{k\_core} = \frac{6.0mils \times 25.4}{\left(6.0mils \times 25.4 - 2 \times 2.5\mu m\right)} \times 3.08 = 3.18$$

Determine Sphere Radius (r) & Base Area (A_{flat})



Drum-side



Matte-side

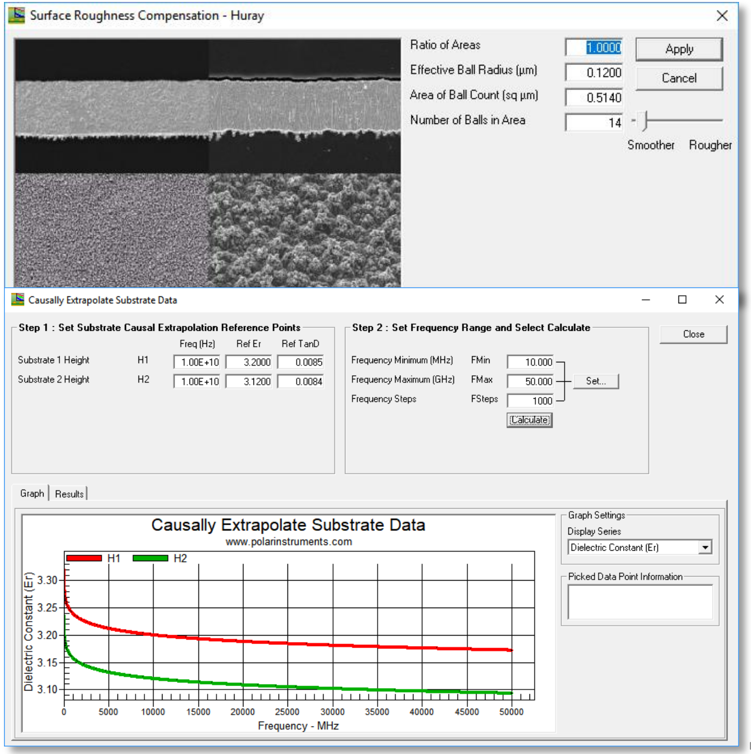
$$r_{drum} \approx 0.06 R_{z\_drum} \approx 0.090\,\mu m$$

$$r_{matte} \approx 0.06 R_{z\_matte} \approx 0.149\,\mu m$$

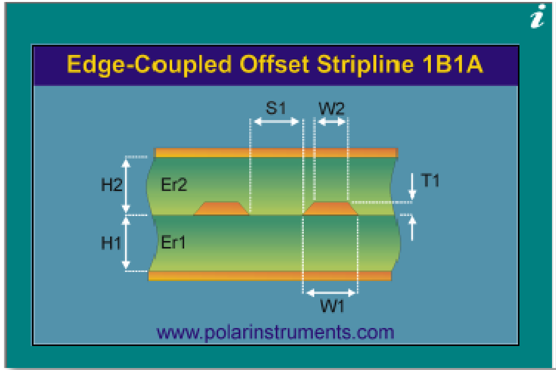
$$r_{eff} \approx \frac{r_{matte} + r_{drum}}{2} \approx 0.120\,\mu m$$

$$A_{flat} \approx 36\left(r_{eff}\right)^2 \approx 0.514\,\mu m^2$$

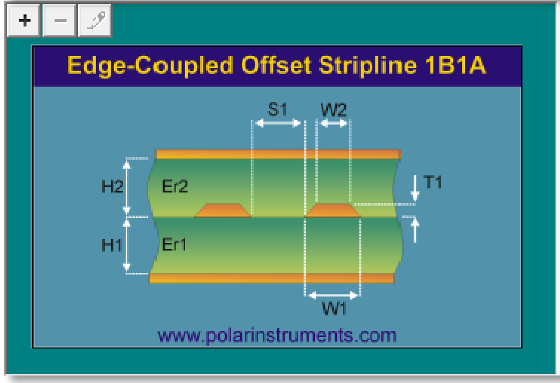
Polar ExaMax Daughter Card SE Trace Parameters



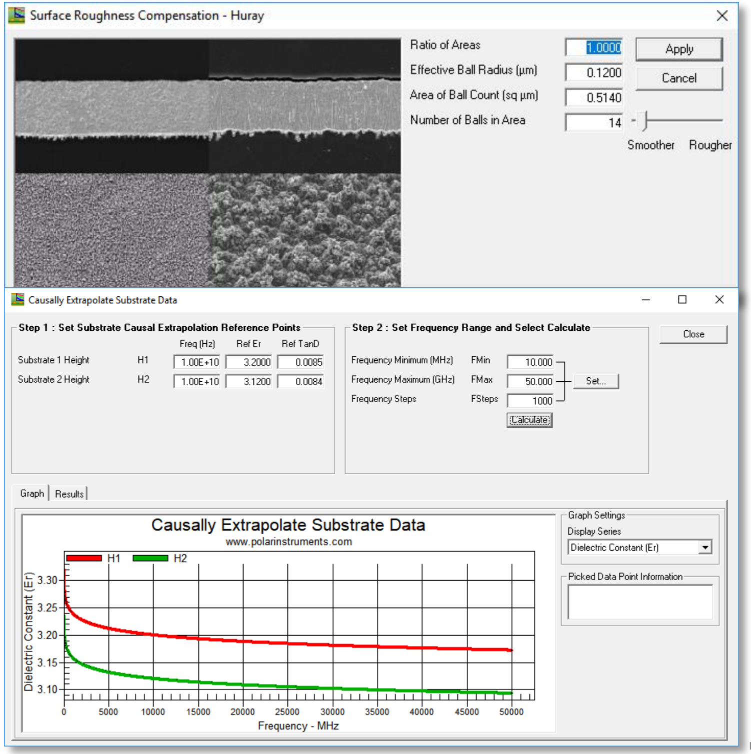
Polar ExaMax Daughter Card Diff Trace Parameters



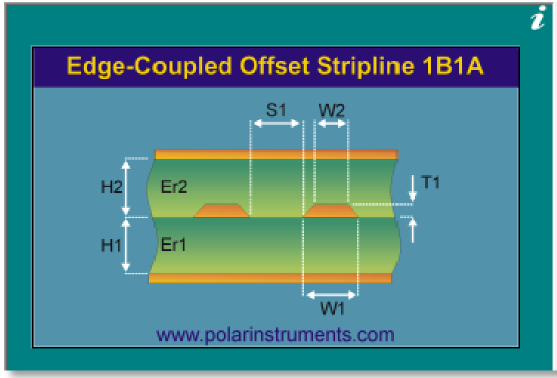
Length of Line	LL	5600.00
Trace Conductivity (S/m)	TC	5.80E+07
Loss Tangent	TanD	0.0195
Rise Time (ps)	Tr	10
Frequency Minimum (MHz)	FMin	10.000
Frequency Maximum (GHz)	FMax	50.000
Frequency Steps	FSteps	1000
Auto Calc		Calculate



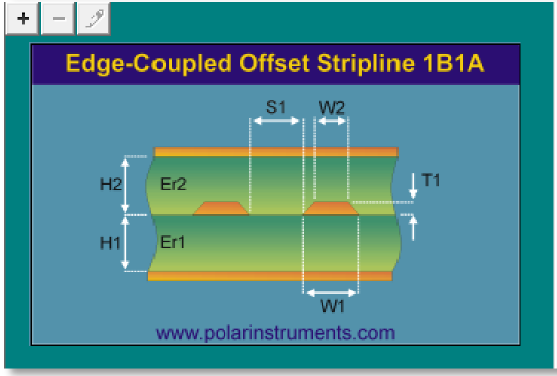
Substrate 1 Height	H1	4.0000
Substrate 1 Dielectric	Er1	3.2000
Substrate 2 Height	H2	6.4000
Substrate 2 Dielectric	Er2	3.1200
Lower Trace Width	W1	4.9000
Upper Trace Width	W2	4.3000
Trace Separation	S1	6.1000
Trace Thickness	T1	0.6000
Differential Impedance	**Zdiff**	**97.25**



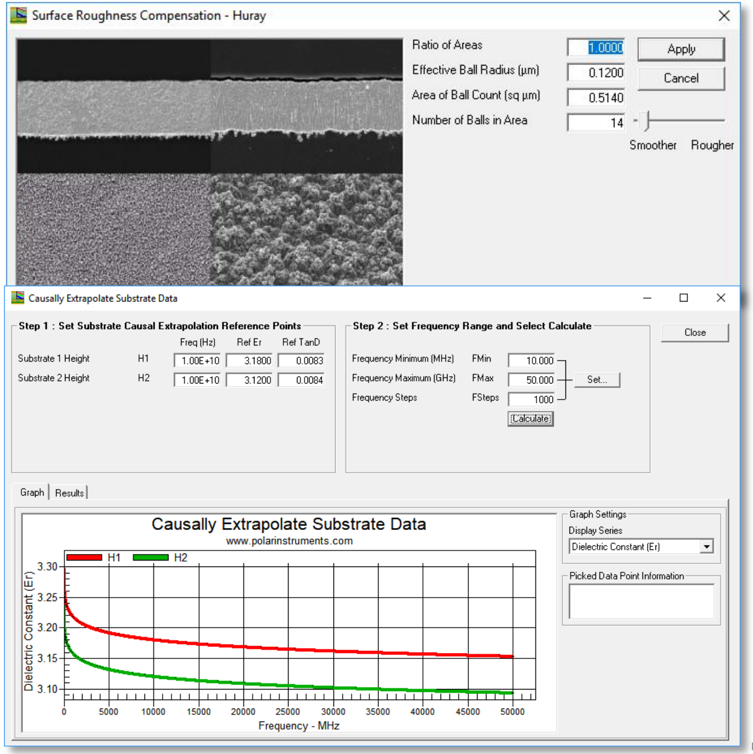
Polar ExaMax Backplane Diff Trace Parameters



Length of Line	LL **	8250.00
Trace Conductivity (S/m)	TC	5.80E+07
Loss Tangent	TanD	0.0195
Rise Time (ps)	Tr	10
Frequency Minimum (MHz)	FMin	10.000
Frequency Maximum (GHz)	FMax	50.000
Frequency Steps	FSteps	1000
Auto Calc		Calculate

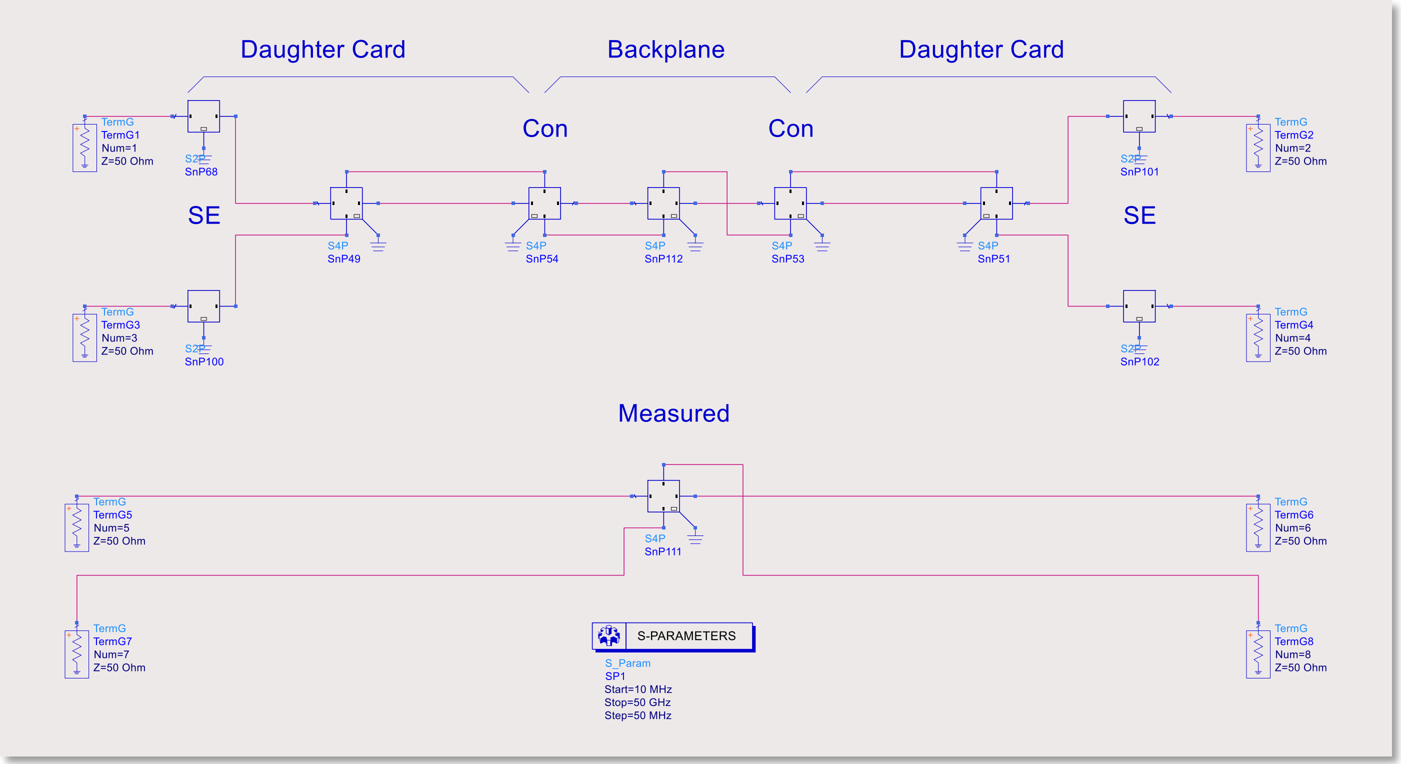


Substrate 1 Height	H1	6.0000
Substrate 1 Dielectric	Er1	3.1800
Substrate 2 Height	H2	6.4000
Substrate 2 Dielectric	Er2	3.1200
Lower Trace Width	W1	6.3000
Upper Trace Width	W2	5.7000
Trace Separation	S1	5.7000
Trace Thickness	T1	0.6000
Differential Impedance	**Zdiff**	**93.88**



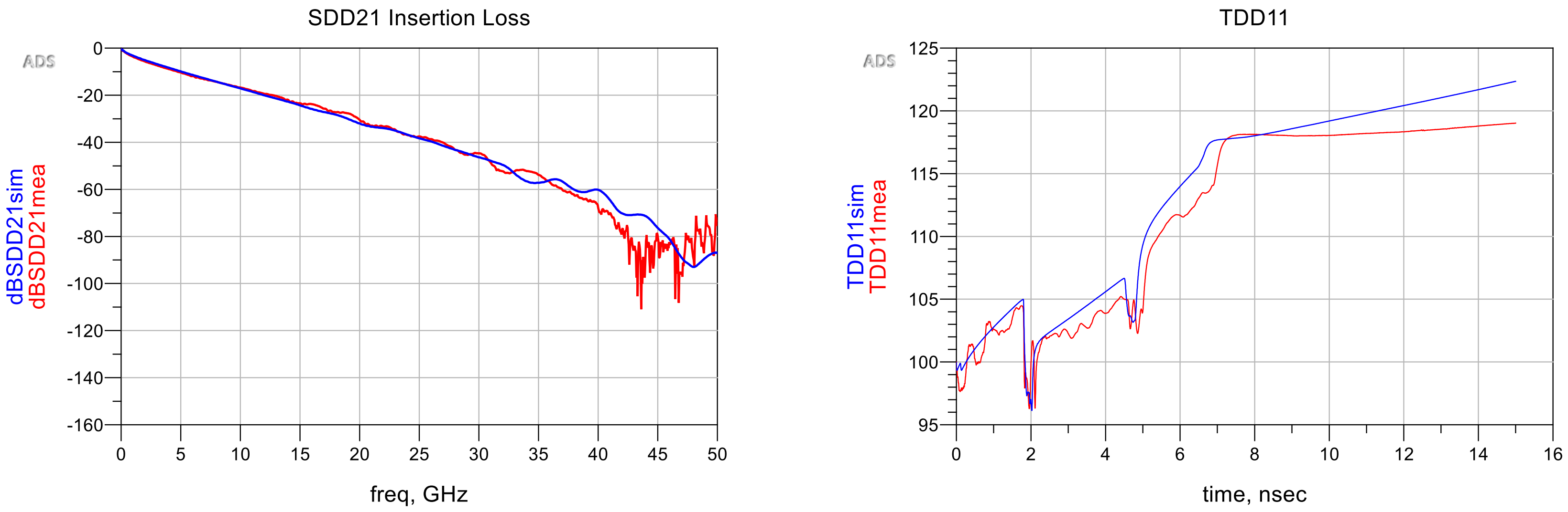
**Length of Line (LL) Adjusted for 8.25”; 14.80”; 20.22”; 26.70”

Generic Topology Model



Modeled with Keysight ADS [13]

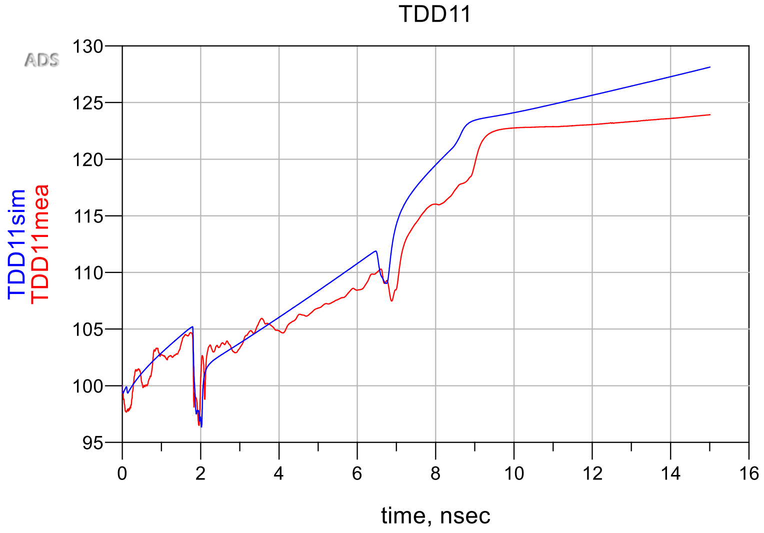
ExaMax Backplane Case 1 Total Length = 20.25”



---- Measured
---- Simulated

Simulated with Keysight ADS [13]

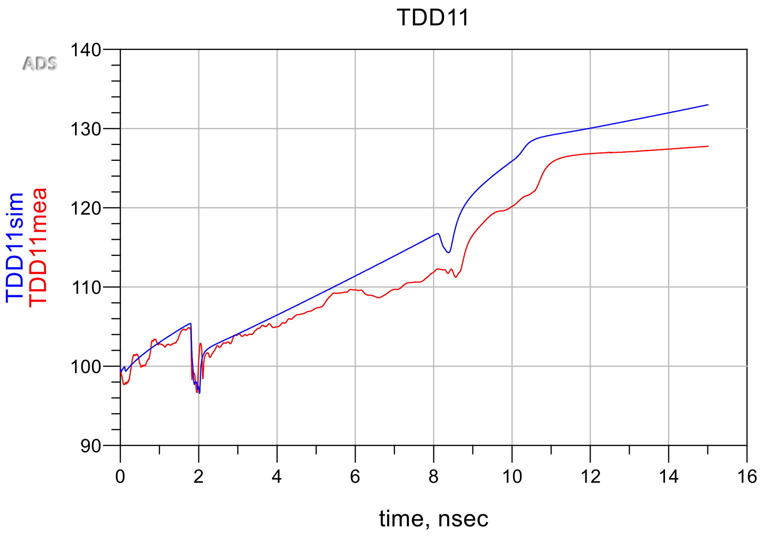
ExaMax Backplane Case 2 Total Length = 26.80”



---- Measured
---- Simulated

Simulated with Keysight ADS [13]

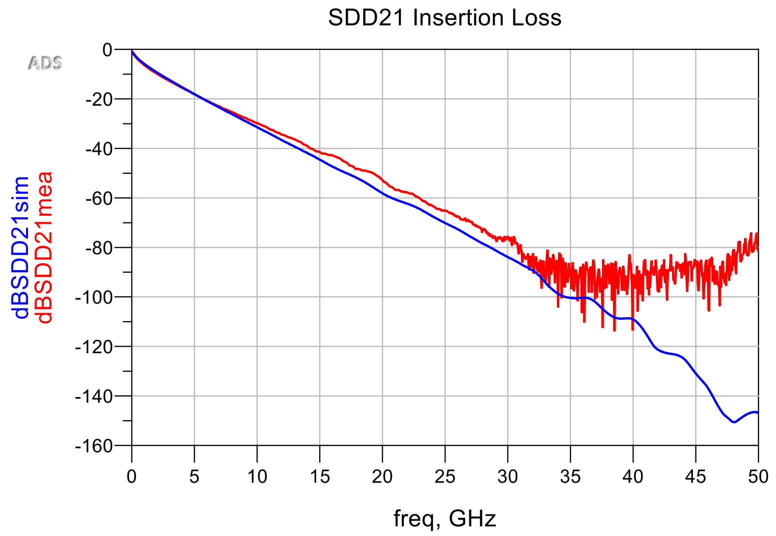
ExaMax Backplane Case 3 Total Length = 32.22”

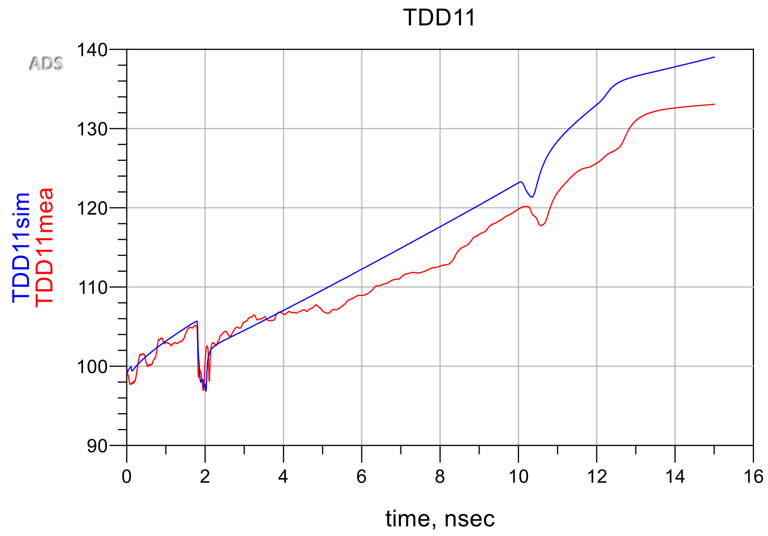


---- Measured
---- Simulated

Simulated with Keysight ADS [13]

ExaMax Backplane Case 4 Total Length = 38.70”

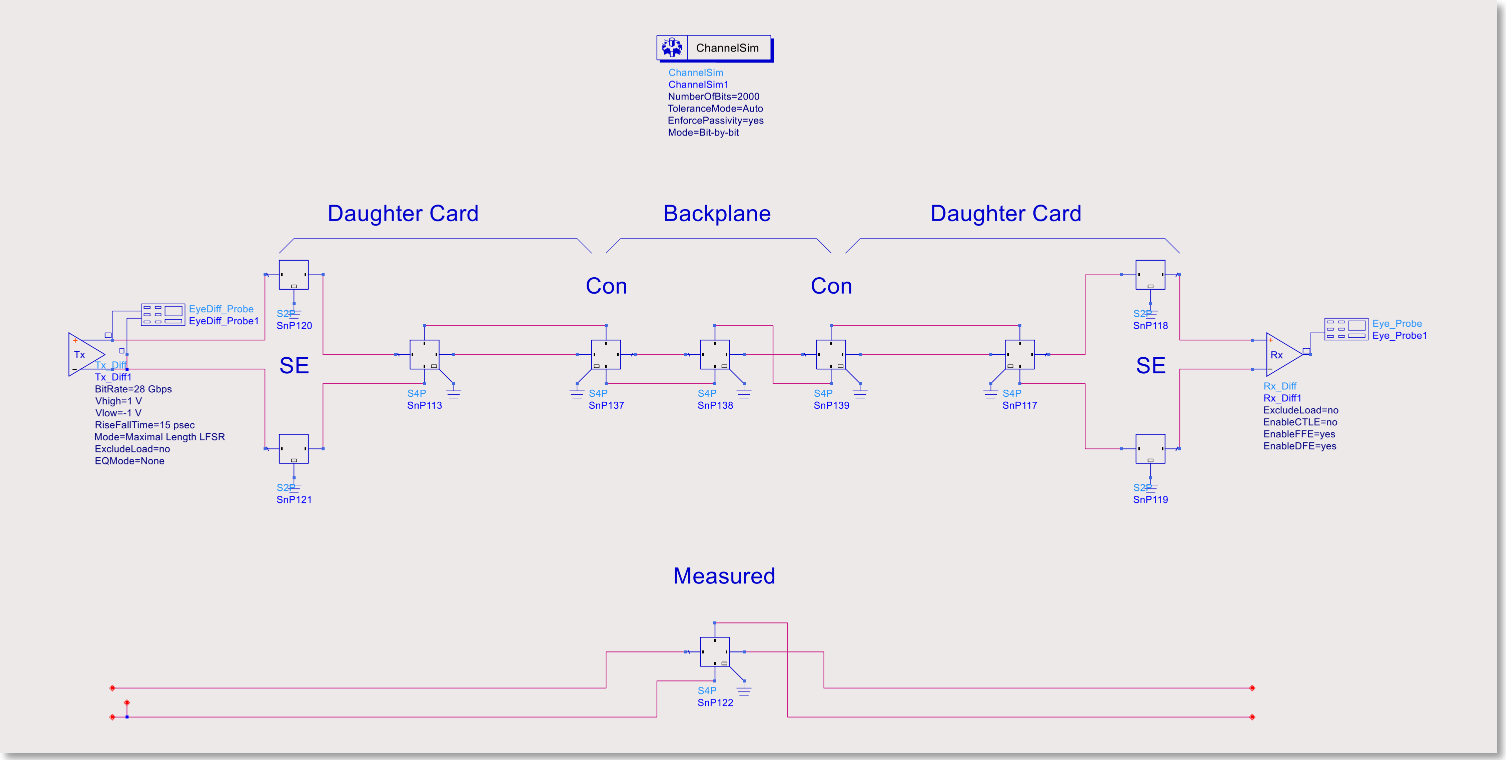




---- Measured
---- Simulated

Simulated with Keysight ADS [13]

Generic Channel Model

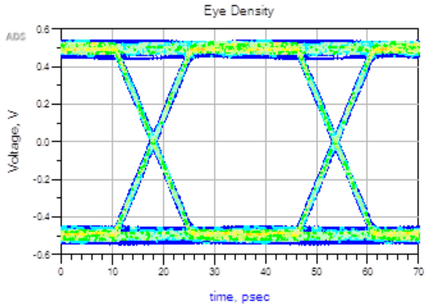


Modeled with Keysight ADS [13]

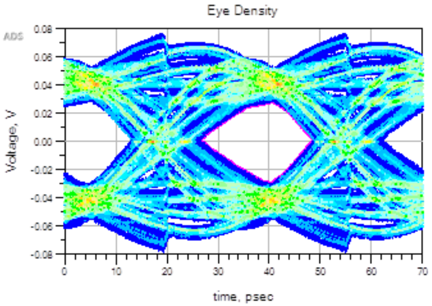
Channel Simulation 28 GB/s Case 1 Total Length = 20.25”

Simulated

Height @ BER
0.909V

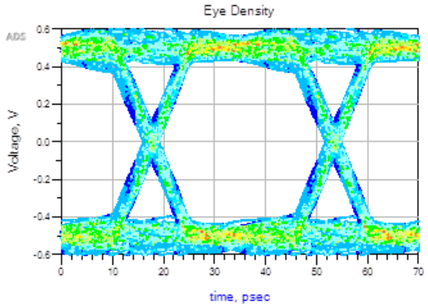


Height @ BER
57mV
Width @ BER
22.32 ps

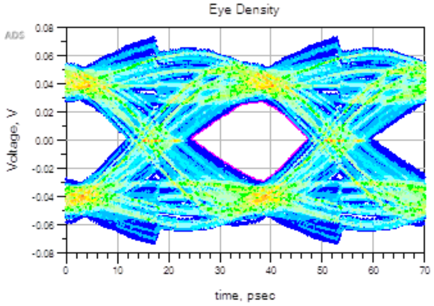


Measured

Height @ BER
0.871V



Height @ BER
57mV
Width @ BER
23.75 ps

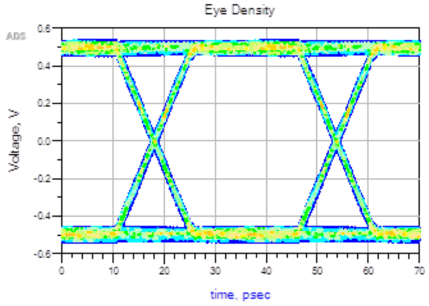


Simulated with Keysight ADS [13]

Channel Simulation 28 GB/s Case 4 Total Length = 38.7”

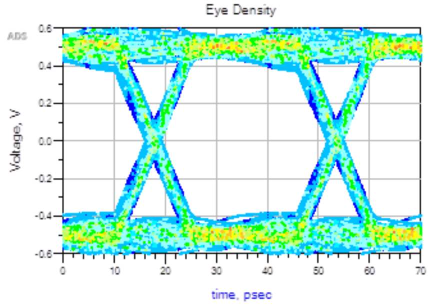
Simulated

Height @ BER
0.923V

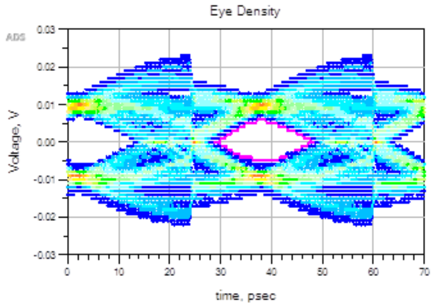


Measured

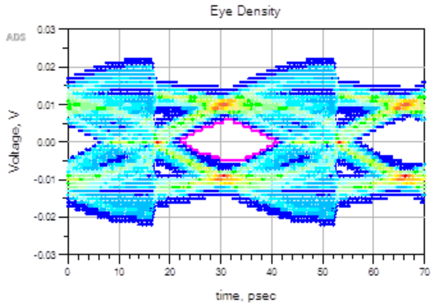
Height @ BER
0.874V



Height @ BER
11mV
Width @ BER
20.00 ps



Height @ BER
11mV
Width @ BER
19.82ps



Simulated with Keysight ADS [13]

Summary

By using Cannonball-Huray model, with copper foil roughness and dielectric material properties obtained solely from manufacturers' data sheets, a practical method of modeling high-speed differential channels is now achievable using commercial field-solving software employing Huray model.

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Thank You!

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